

Scintillation Tile Hodoscope for the PANDA Barrel Time-Of-Flight Detector

William Nalti, Ken Suzuki, Stefan-Meyer-Institut, ÖAW
on behalf of the PANDA/Barrel-TOF(SciTil) group

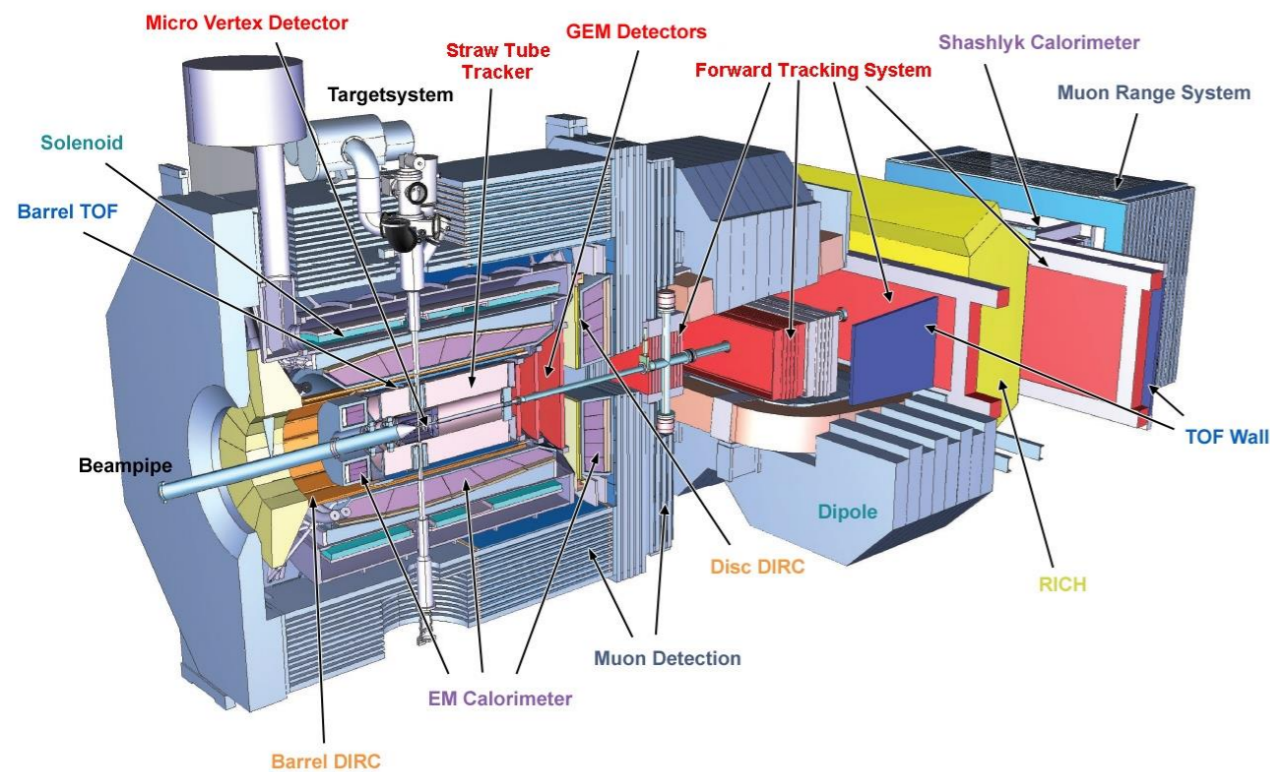
12.06.2018, ICASiPM2018

Outline

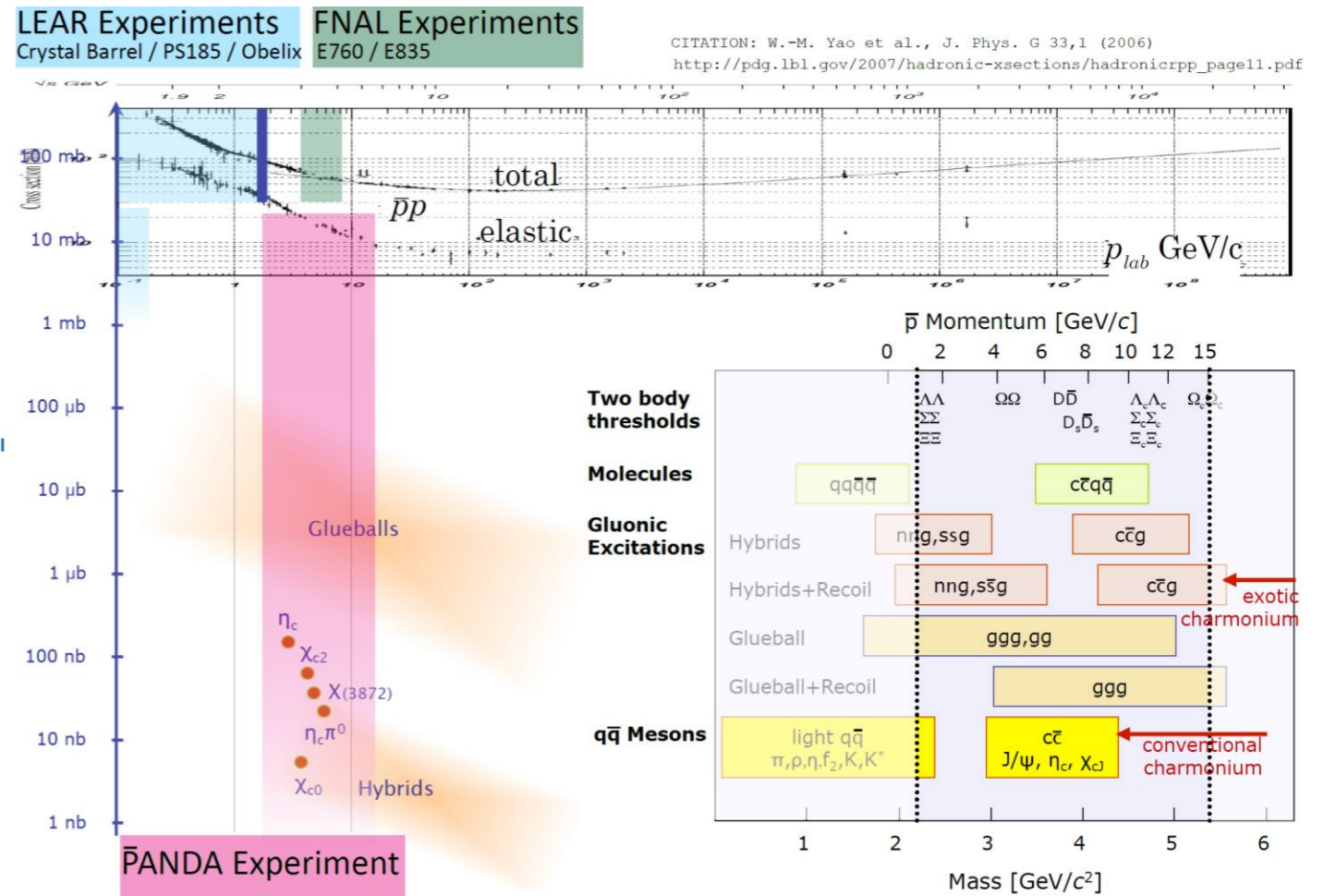
- Introduction: PANDA & FAIR
- Barrel TOF Design
- Single Tile Performance
- Larger Scale Integration

Tomorrow 11.45: Application of SiPMs and MCP-PMTs in the PANDA PID detectors - Albert Lehmann (Erlangen University)

PANDA Experiment at FAIR



MVD < STT < B-DIRC < B-TOF < EMC



Installation planned end-2021, with physics starting 2025

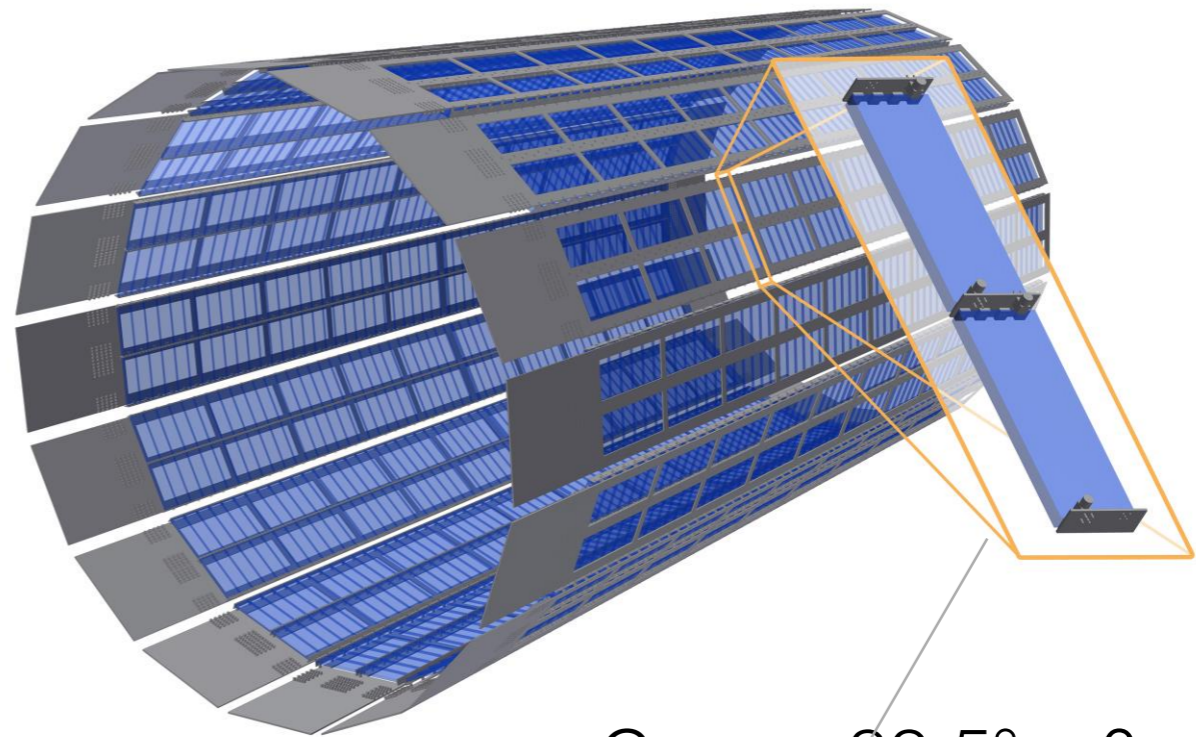
Barrel Time-of-Flight (TOF) Design

2.46m long, 1m diameter

16 Super modules

240 ch. /SM

max. 40 kHz /ch.



Covers $22.5^\circ < \theta < 140^\circ$

180x18 cm² scintillators (120x) area

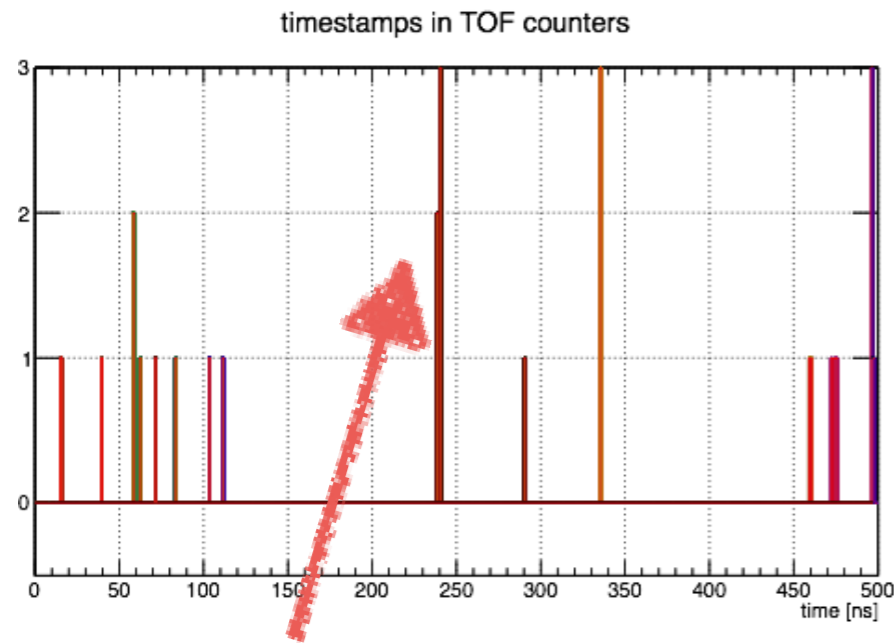
2 ch./scint.

rest is left for FEE

Scintillator Tile

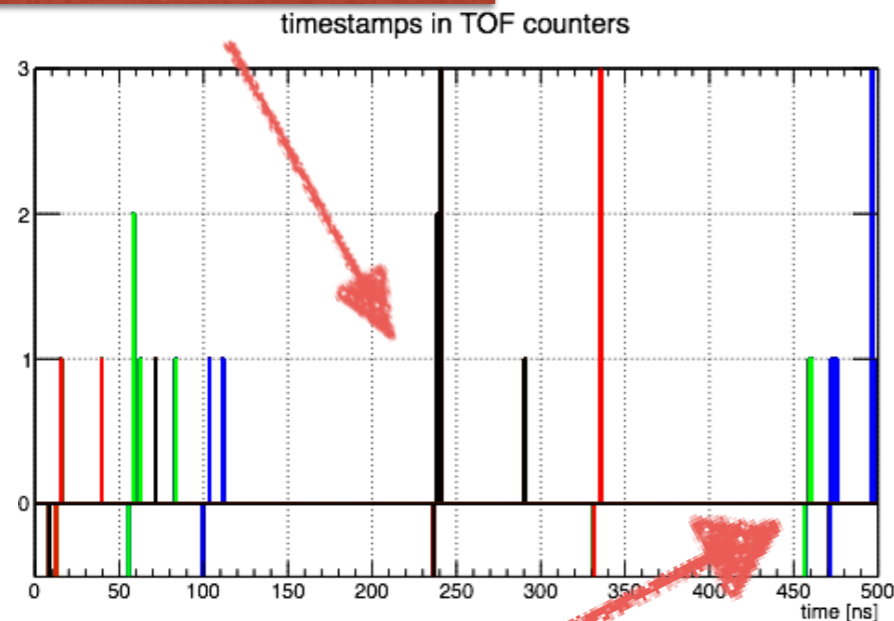
Total: 1920 tiles, 3840 channels, 15360 SiPMs

Capabilities and Requirements

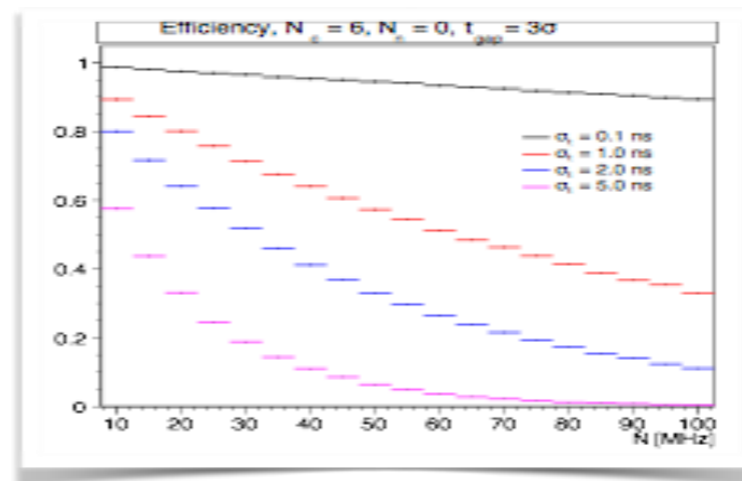


- Collision time determination
- event sorting
- 20 MHz interaction rate
- particle identification (PID)

“hits” in detector

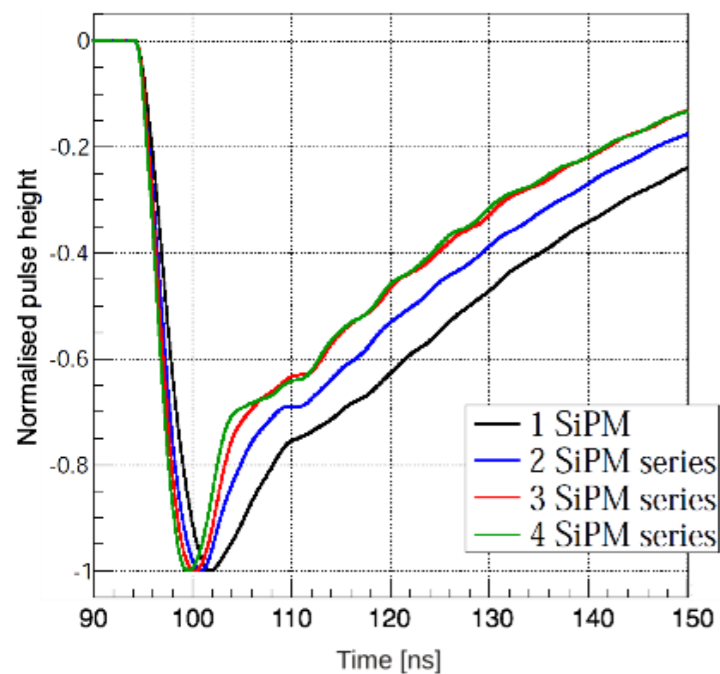
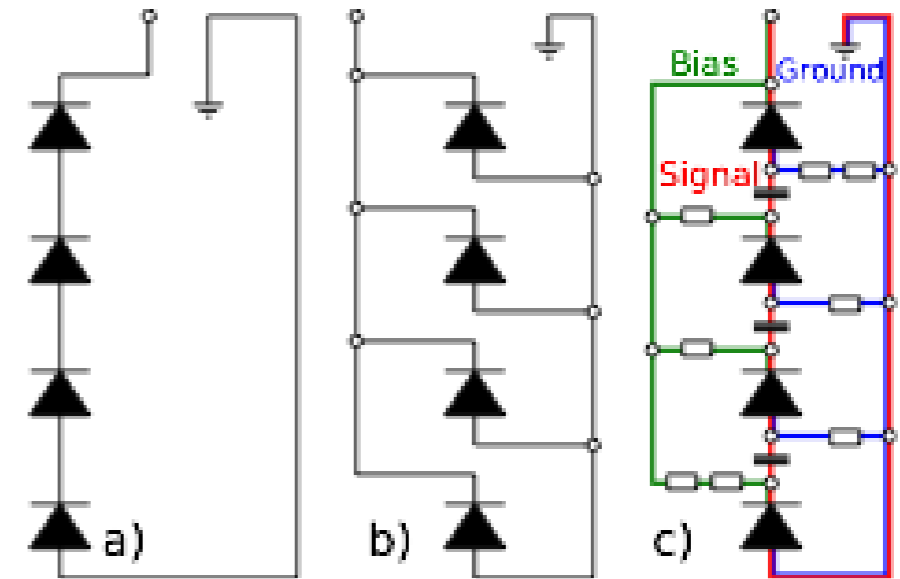
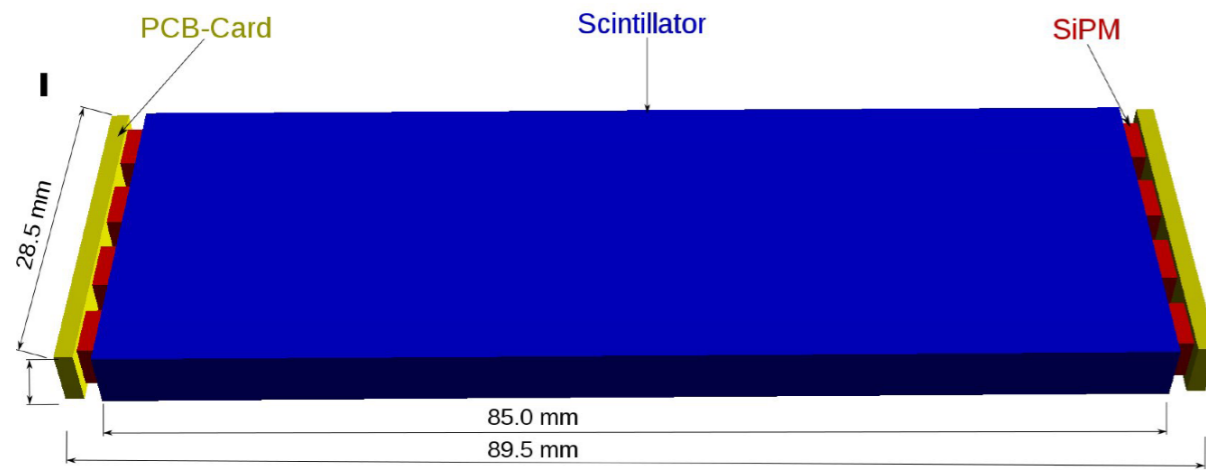


collisions



Requirement: $\sigma_t < 100$ ps
to keep the efficiency loss due to event mixing in a tolerable level

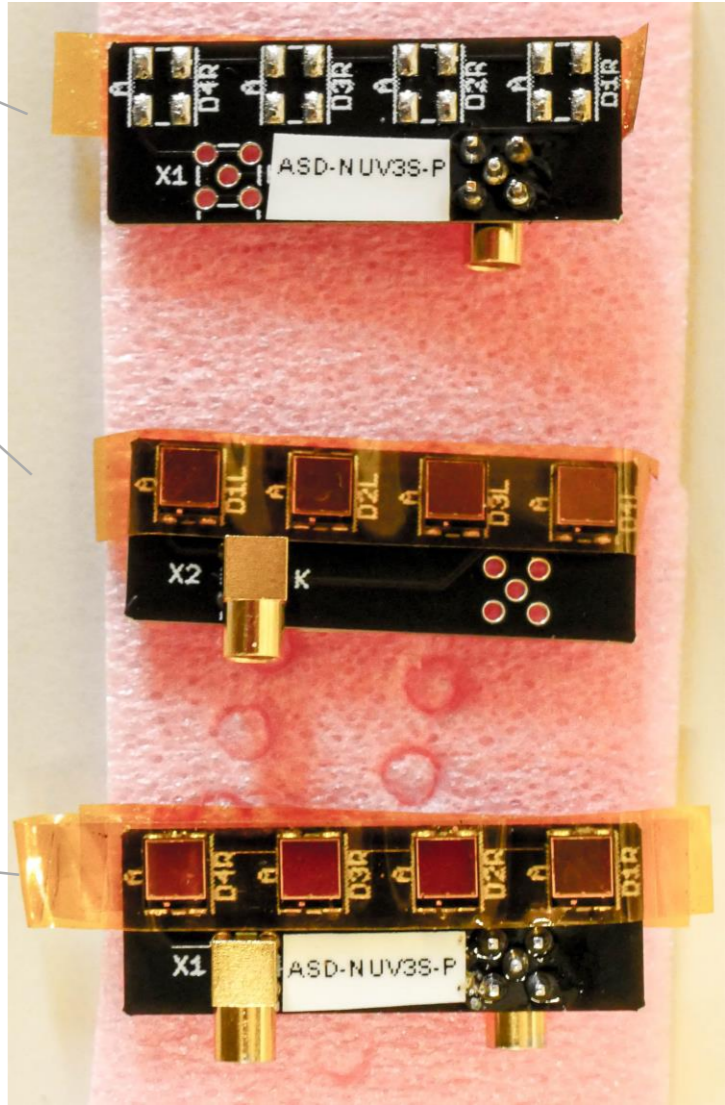
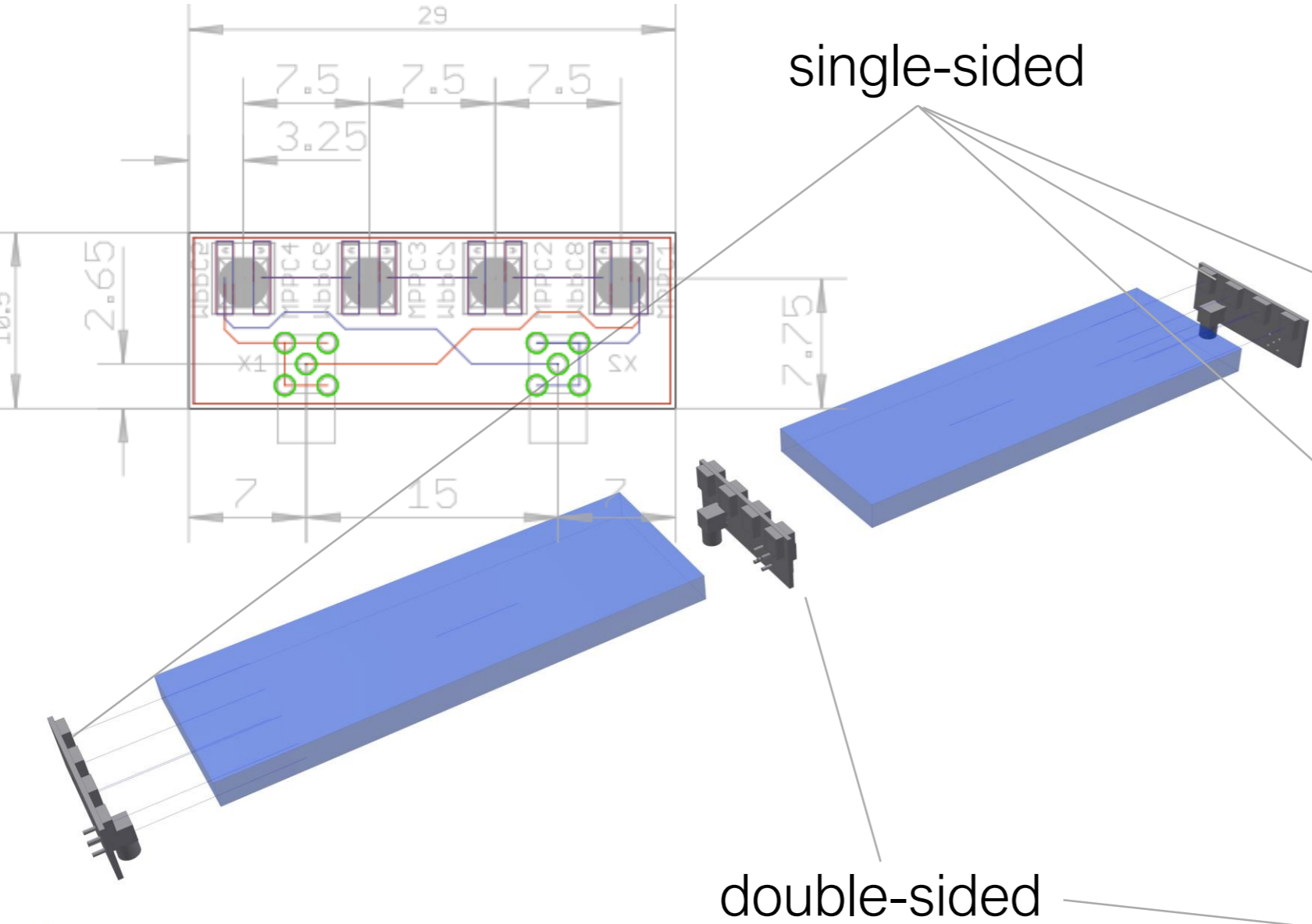
Single Tile Design



	Sensitive area	Bias Voltage	Signal shape	Gain	V_{BD} adjustment
Single	1	$V_{br} + OV$	-	1	-
Series	N	$N \times (V_{br} + OV)$	faster	$1/C$	Yes
Parallel	N	$V_{br} + OV$	slower	C	No
Hybrid	N	$V_{br} + OV$	faster	$1/C$	No

Table 4.1: Comparison of series, parallel and hybrid connections of N SiPMs with reference of a single sensor.

Dual Module



MMCX connector

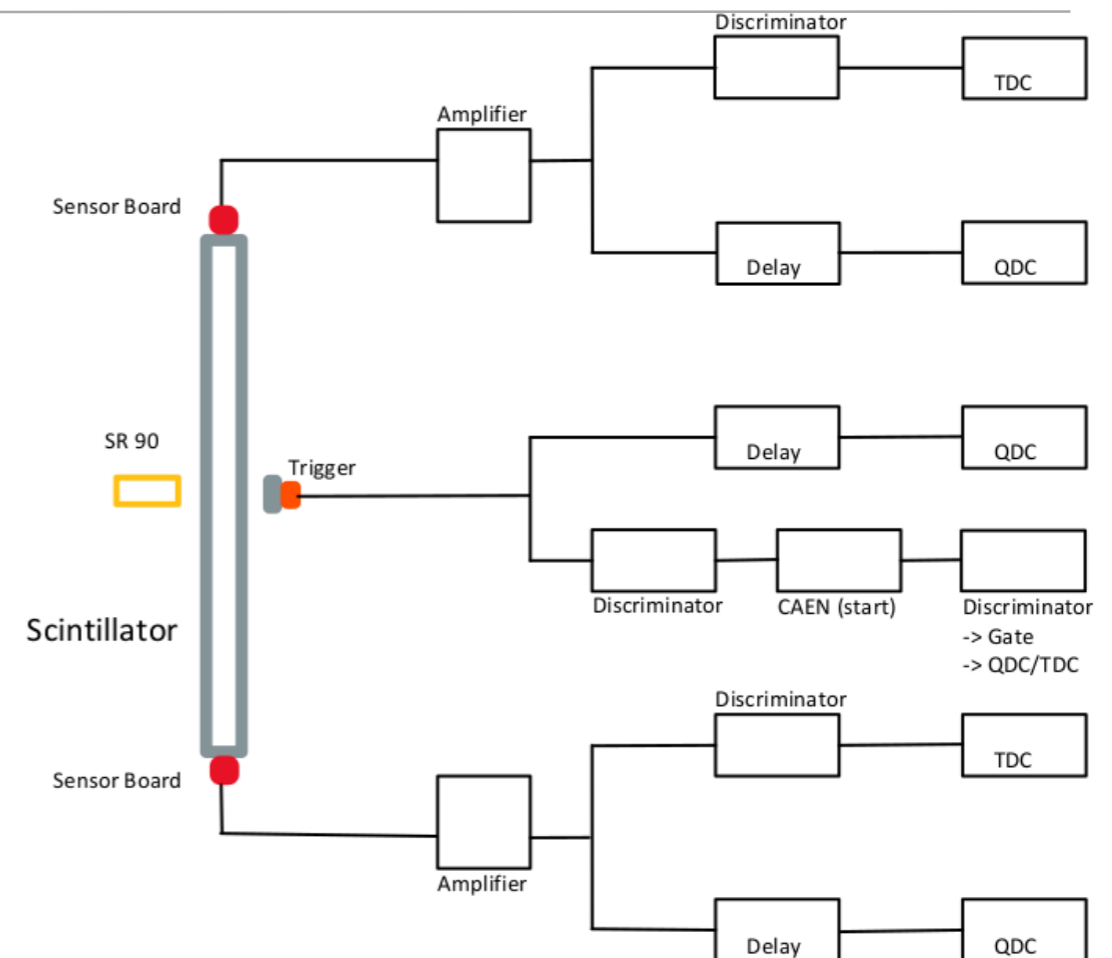
Performance - single tile

- Optimization of time-resolution in terms of material, wrapping, threshold, overvoltage

Wrapping material	Time resolution [ps]	Number of detected photons
No wrapping	55.0 ± 0.3	288 ± 2
Aluminised Mylar foil	52.7 ± 0.3	355 ± 2
Tyvek hardstructure 1057D	55.0 ± 0.3	394 ± 3
Enhanced specular reflector (ESR)	55.2 ± 0.3	355 ± 3
Teflon tape	59.4 ± 0.3	408 ± 4
aluminium foil	54.2 ± 0.3	344 ± 3

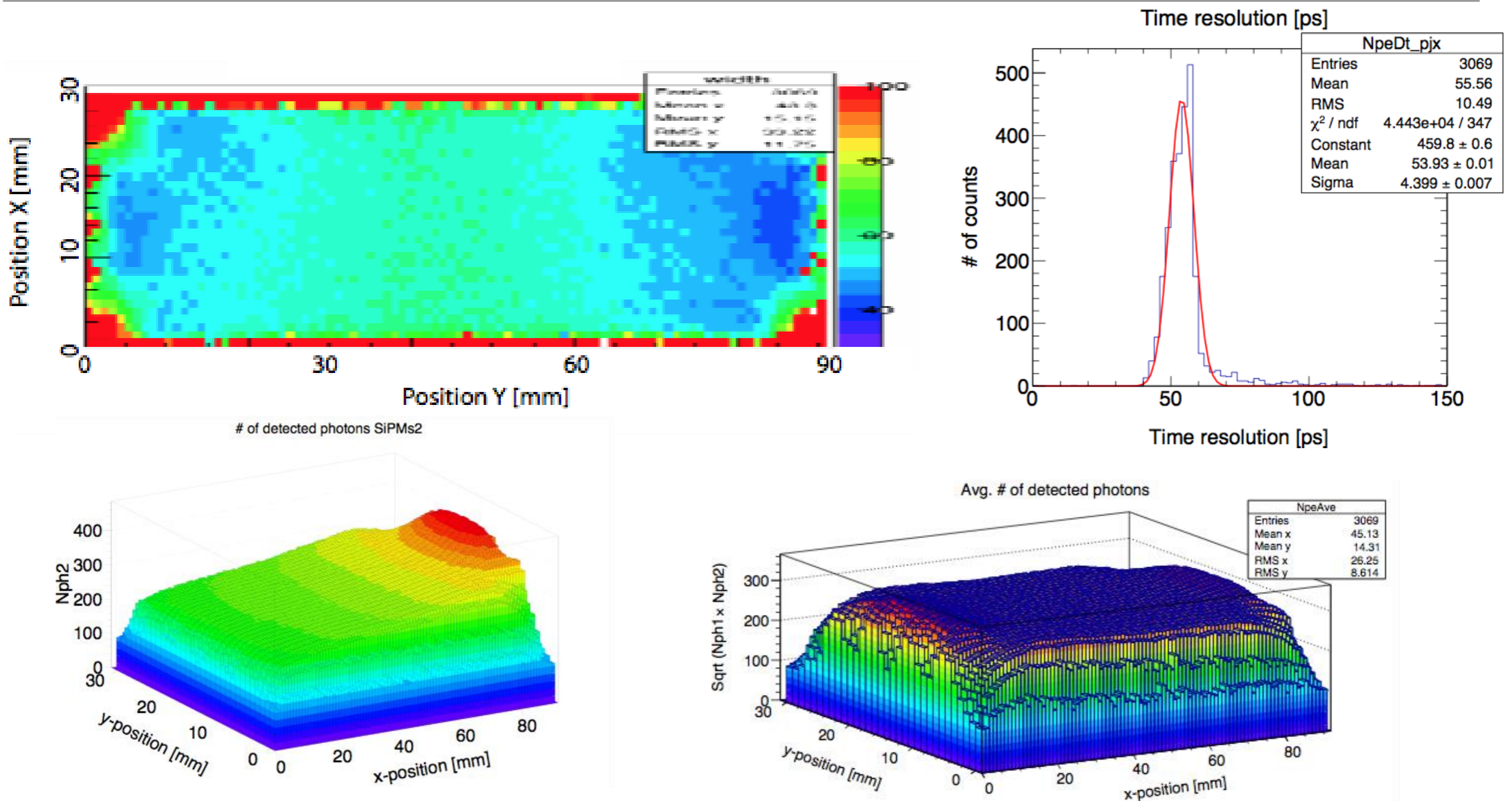
Wrapping material	Time resolution [ps]	Number of detected photons
No wrapping	61.3 ± 0.3	371 ± 2
Aluminised Mylar foil	59.7 ± 0.3	445 ± 3

Very fine position dependence measurement of the performance with the optimised condition with well collimated ^{90}Sr source



In collaboration with Erlangen

Performance - single tile



HV 240V, threshold -30 mV, 2000 events/position, 3069 positions
 Mean time resolution $\sigma = 53.9$ ps

Performance – single Tile

thickness	Npe1	Npe2	time-resolution (ps)
3mm	72.37	46.84	60.34
4mm	85.64	55.14	68.09
5mm	139.94	128.69	50.14
5mm polished	111.87	78.1	48.29
6mm	101.7	70.7	48.7

Side view of the Sensorboard

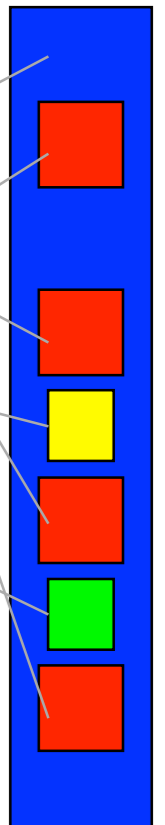
Surface coverage = 1/4

scintillator (28.5x5 mm²)

SiPM (3x3 mm²)

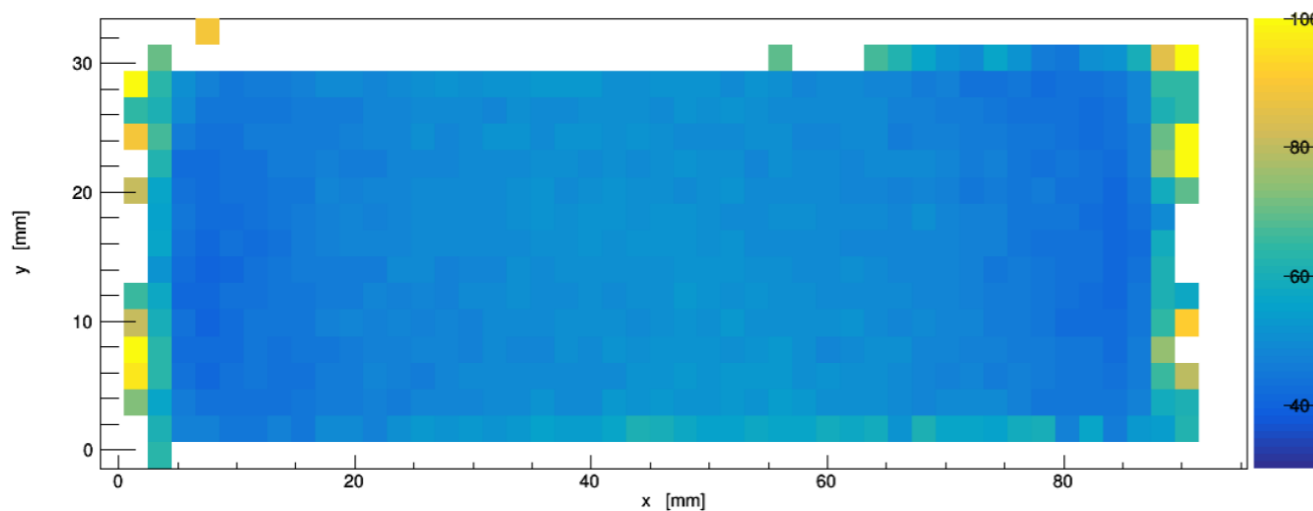
LED

Temperature sensor

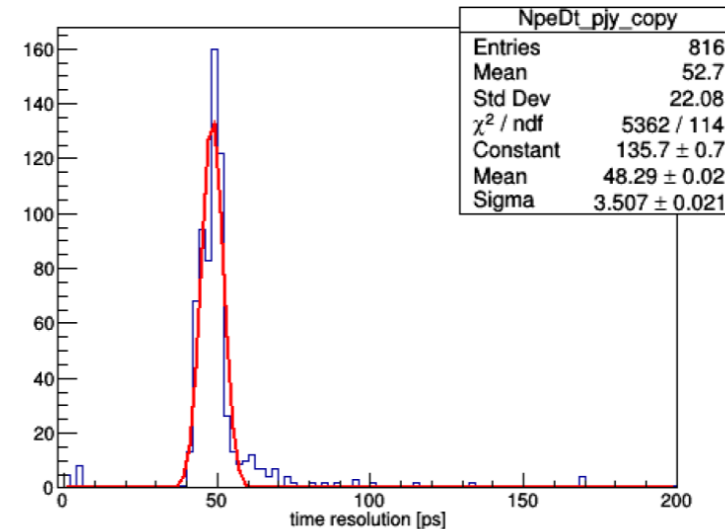


Run 47 / 5 mm polished

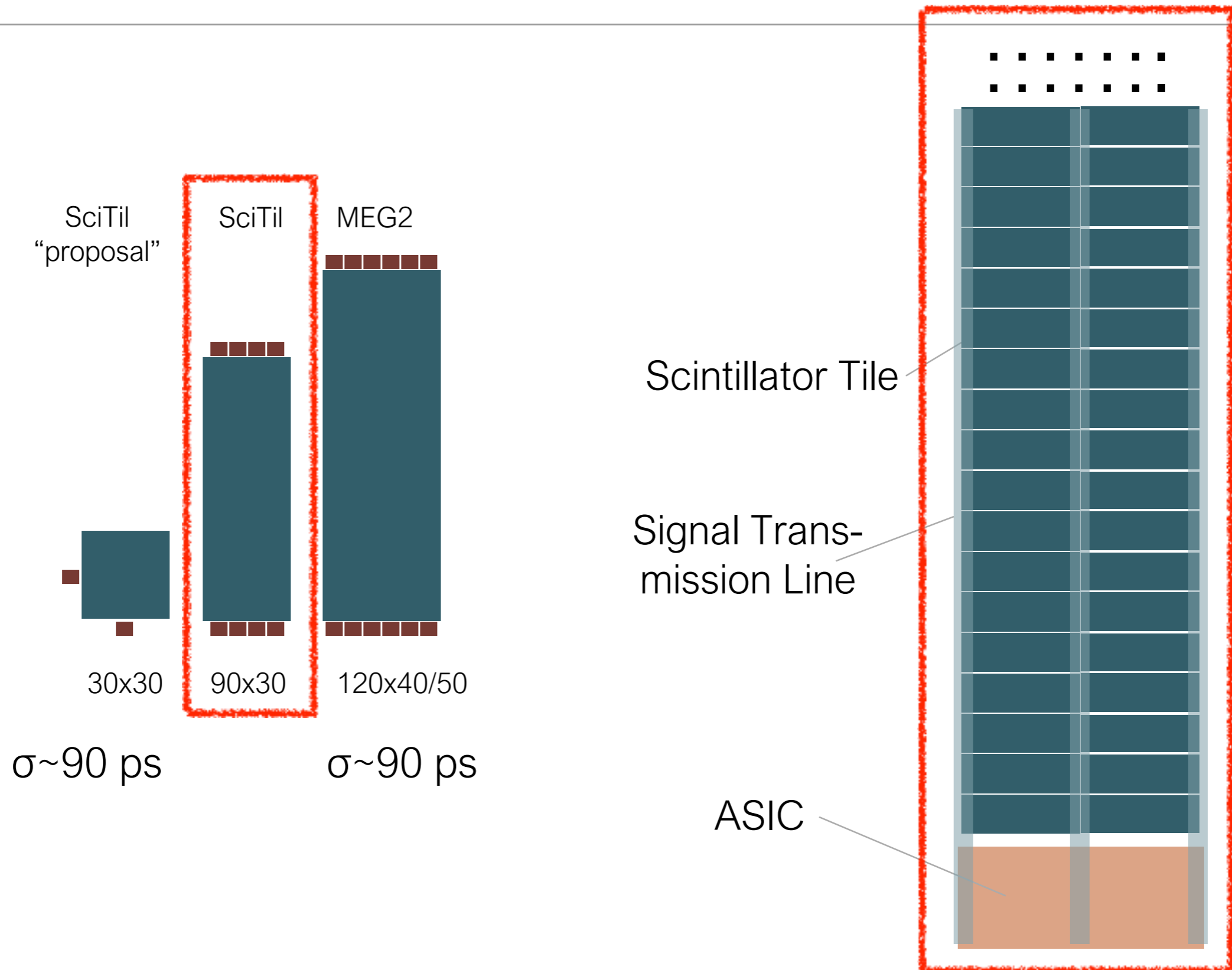
TDiff Resolution



TimeresFit



Barrel Timing Hodoscope, New Design

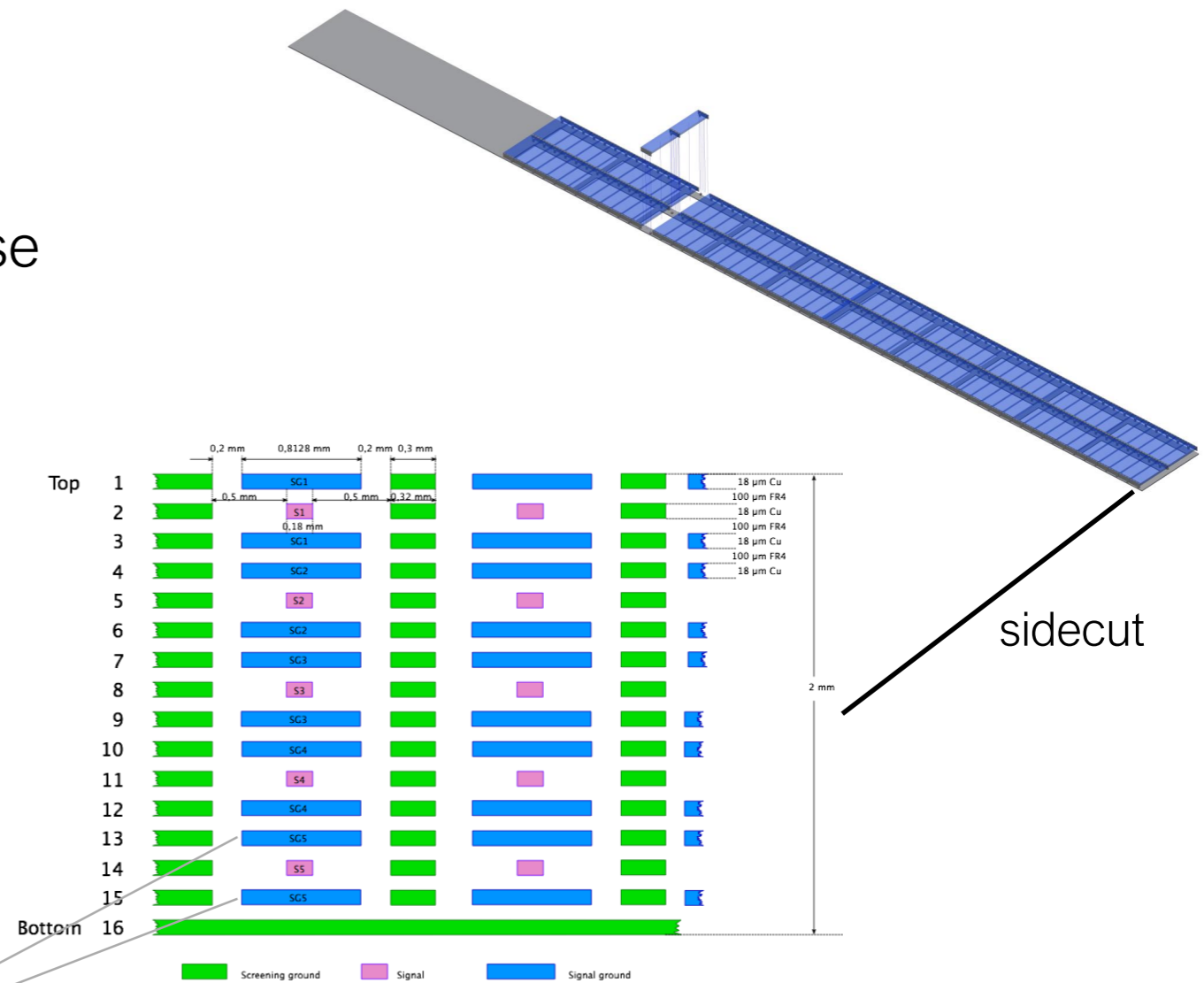


Micro Stripline Technique

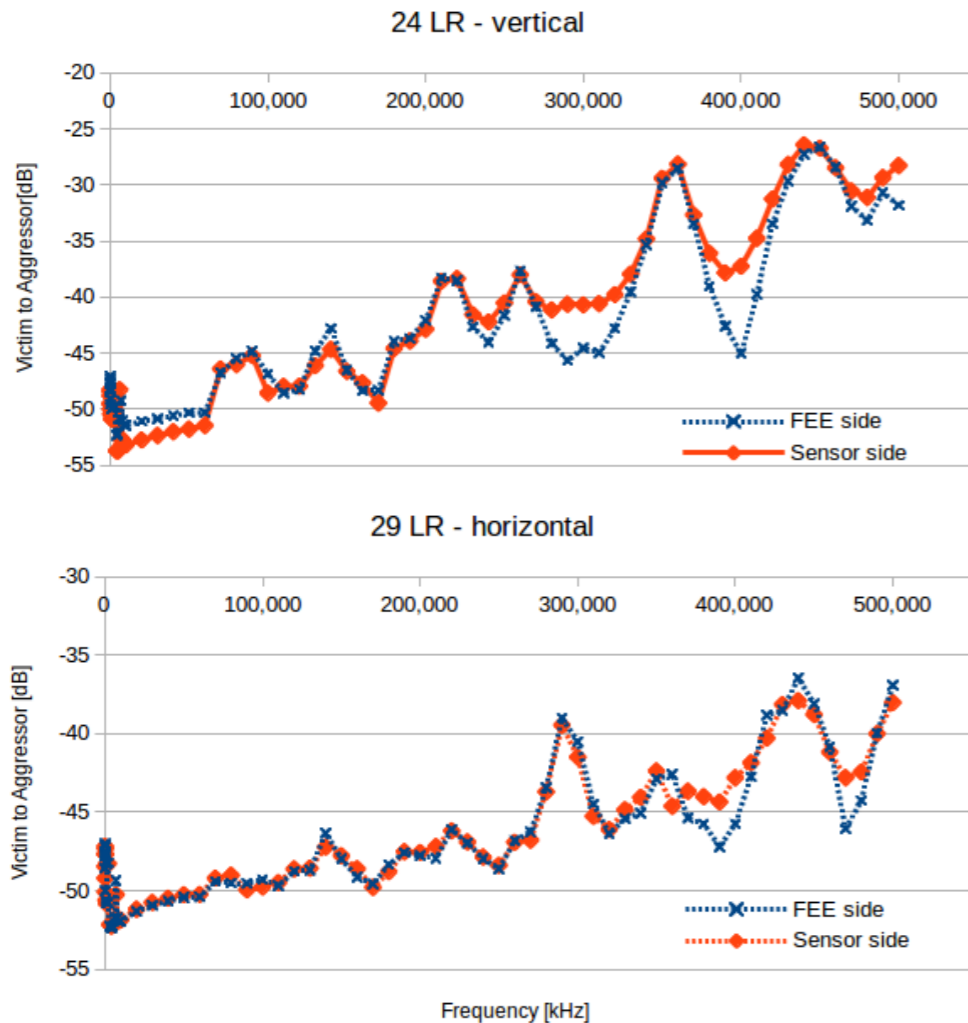
- Coaxial-like structure to transmit signals over a PCB board, realised on a multilayer PCB board, that feature:
 - High density
 - Good shielding from external noise
 - High bandwidth
 - Low crosstalk
 - Mechanical strength

First prototype

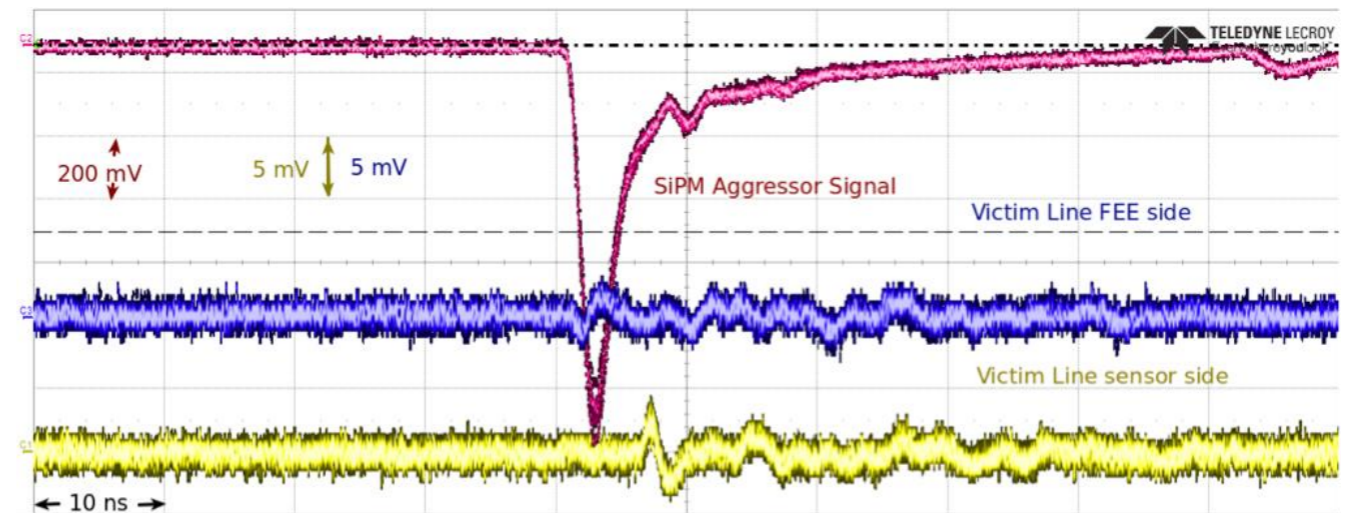
2 GND per line



Crosstalk between the Micro Striplines (Prototype n°1)



1ns rise-time = 350 MHz

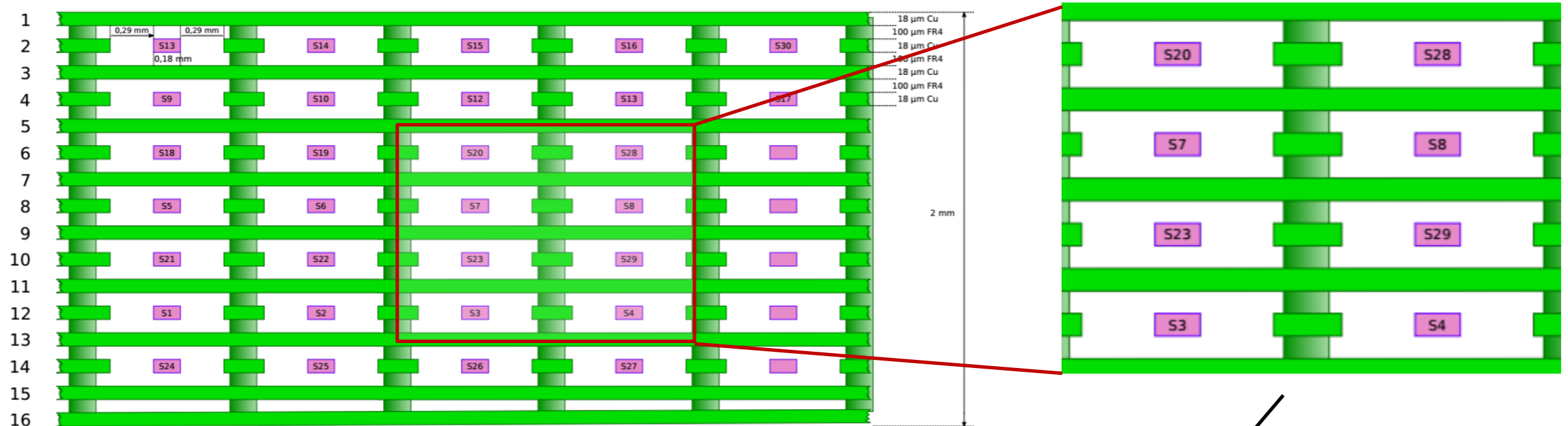


Tested in realistic condition.

Crosstalks can be reduced e.g. by using “via” and/or by optimizing the channel sequence

Probable Best Design

single ground layer interconnected at the board ends



lines shuffled to minimize the distance they share as direct neighbour

design not tested yet, due to considerable manufacture delay. Delivered last week.

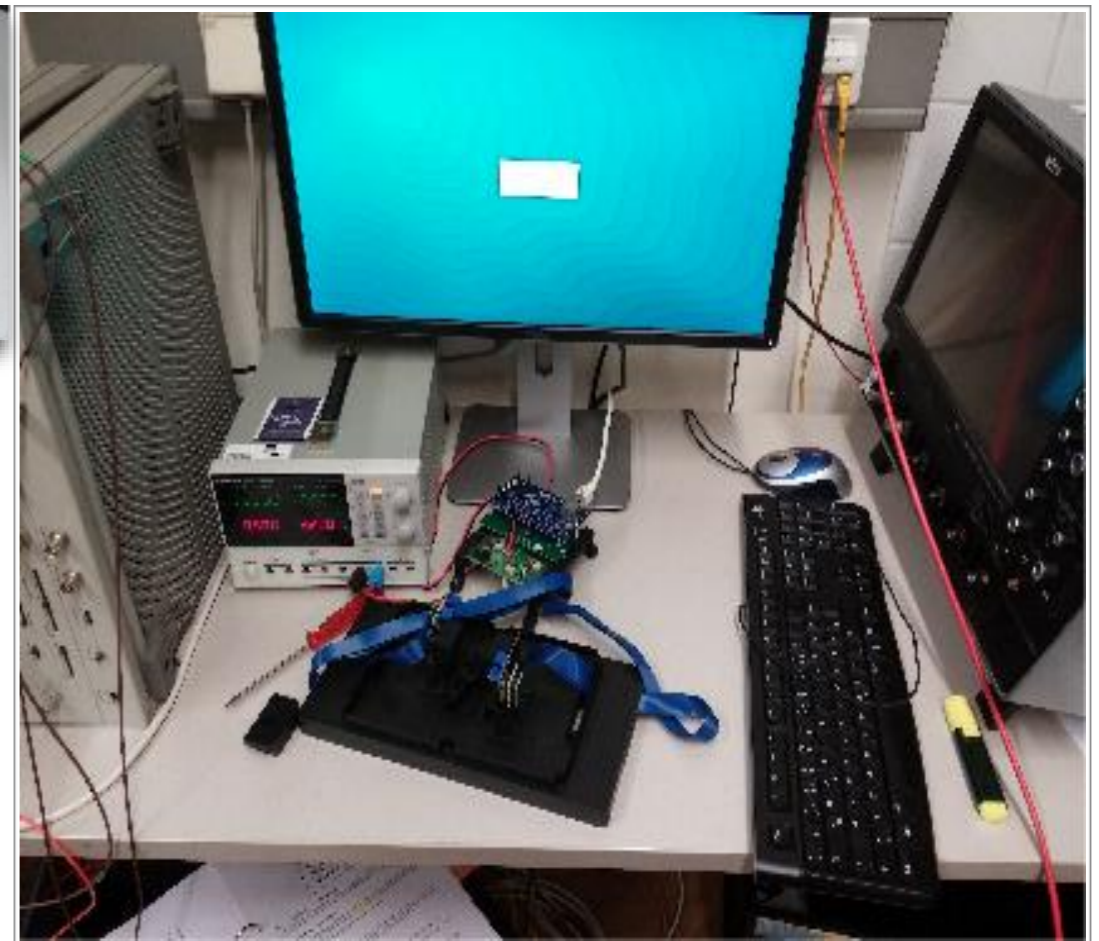
This design = crosstalk reduction? Less copper as prototype 1 = material budget reduction.

due to some spare space on the railboard and no extra cost, few other designs were added and will be tested for comparison

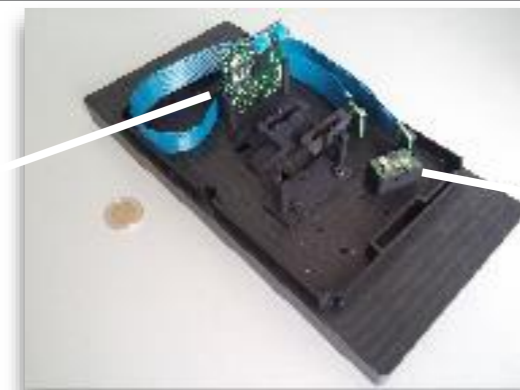
Front End Electronics

66cm allocated for FEE
TOFPET2 ASIC readout

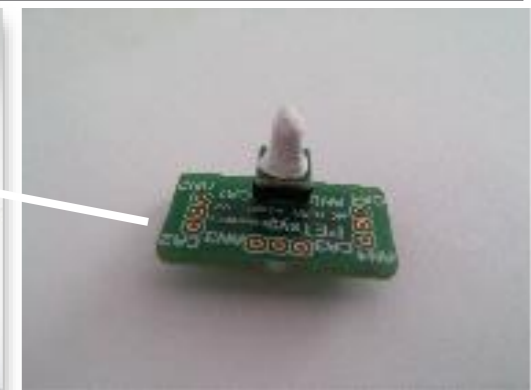
- Signal amplification and discrimination for each of 64 independent channels.
- Dual branch quad-buffered analogue interpolation TDCs for each channel.
- Quad-buffered charge integration for each channel.
- Dynamic range: 1500 pC.
- TDC time binning: 30 ps
- Gain adjustment per channel: 1, 1/2, 1/4, 1/8.
- SiPM family supported: positive or negative signal polarity
- Max channel hit rate: 480 kHz.
- Configurable timing, trigger and ToT thresholds.
- Fully digital output.
- Max output data rate: 2.6 Gb/s.



TOFPET2 ASIC
test board (64ch)



Test assembly with
SiPM and ASIC board



SiPM + LYSO crystal

Summary

- Barrel Time-of-Flight Detector for PANDA
 - 240cm long, 5m² sensitive area, 15.360 SiPM, 2.000 Tiles, 4.000 channels
 - series connection of 4 SiPMs
 - Cable-less design with transmission lines over PCB board
 - $\sigma_t \sim 50$ ps, lab test. Beam test, see talk Albert Lehman (tomorrow 11:45)
- Detector installation ~ 2022

Backup

Performance - single tile

Time resolution depend of Pole Zero Cancelation

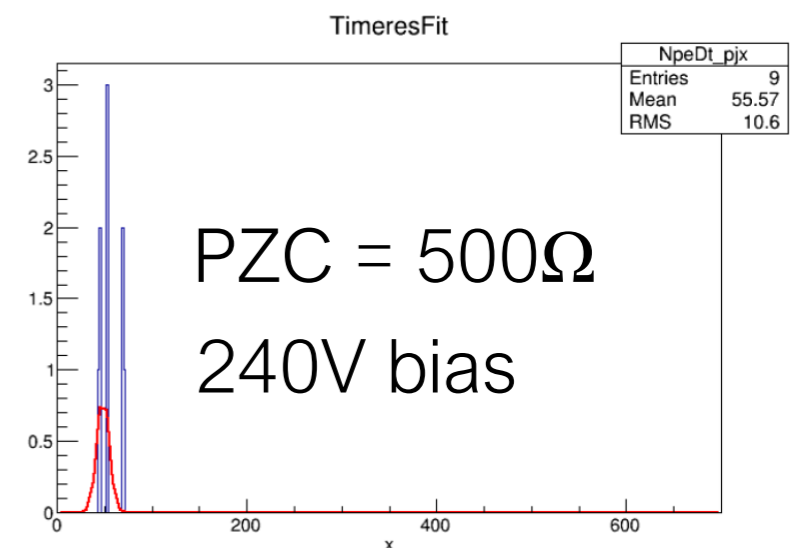
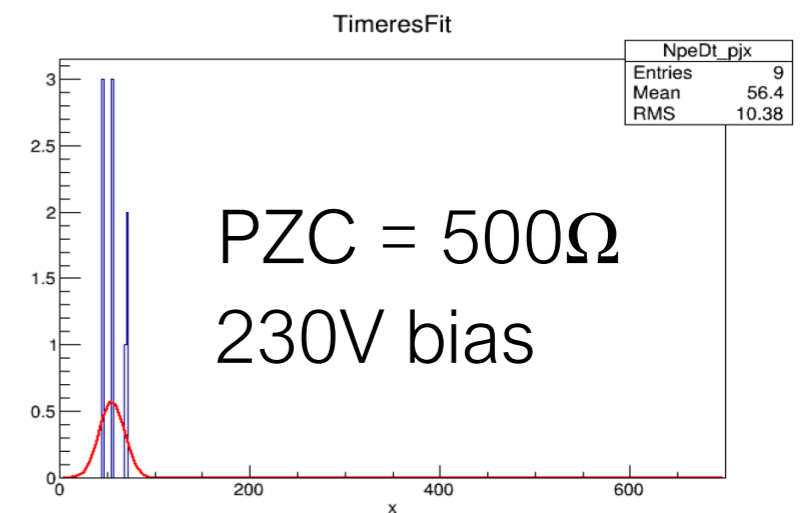
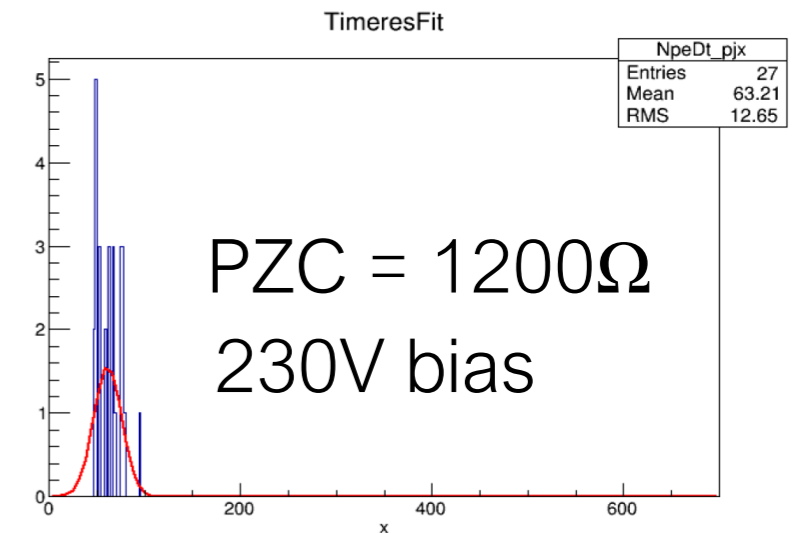
Reproduced in 2017: 63.2ps for 1200 Ω
and 53.4ps for 500 Ω

Bias voltage also has slight impact on time resolution

Threshold scan:

11.3mV : 49,7 +/- 1,9 ps
20mV : 47.0 +/- 2.8 ps
40mV : 48.3 +/- 3.4 ps
50mV : 50.3 +/- 5.0 ps
75mV : 50.3 +/- 3.4 ps

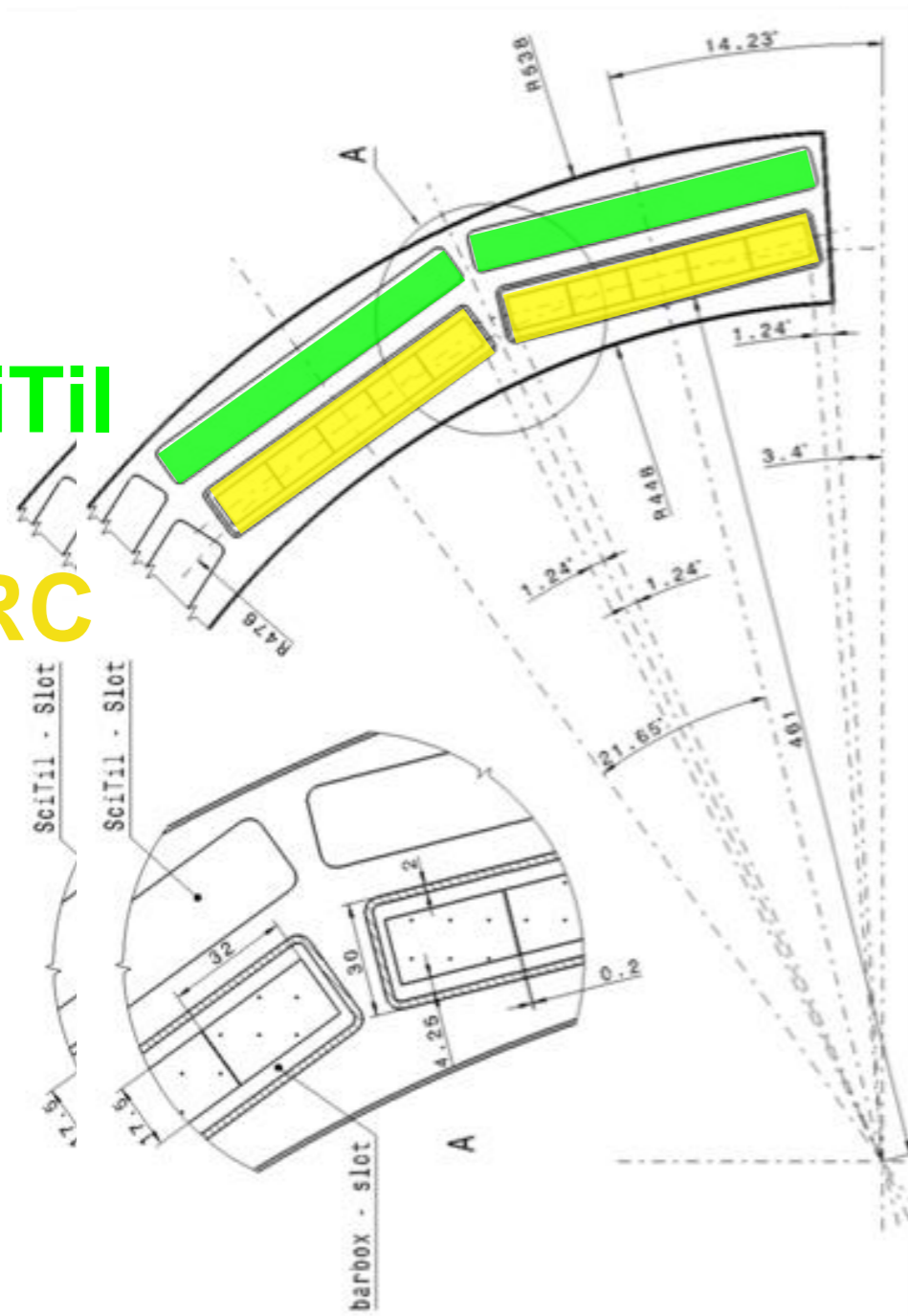
Best time-resolution for 20mV threshold



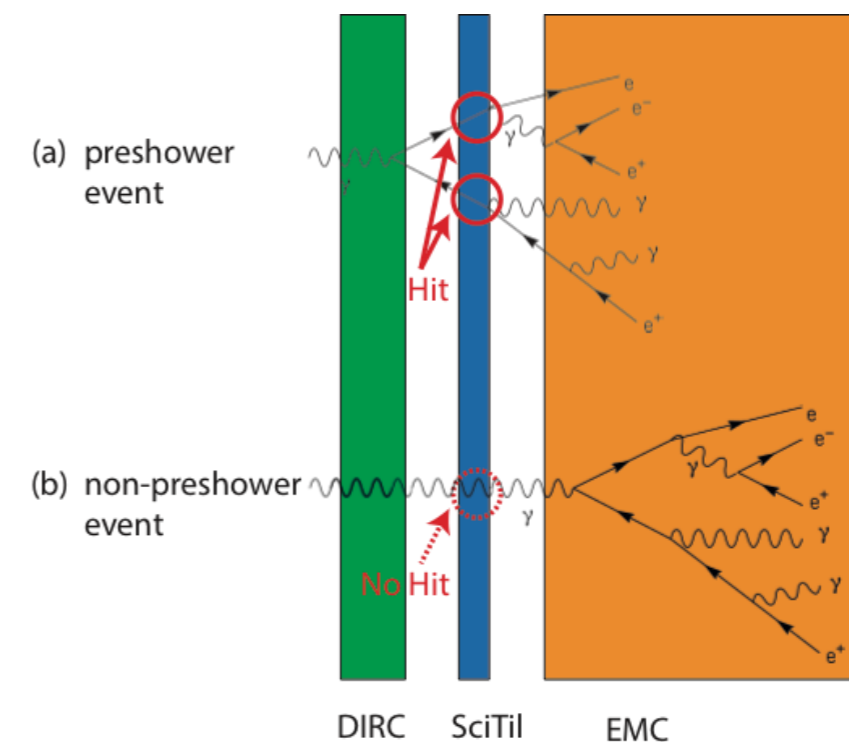
Capabilities and Requirements, and Detector Layout

SciTil

DIRC

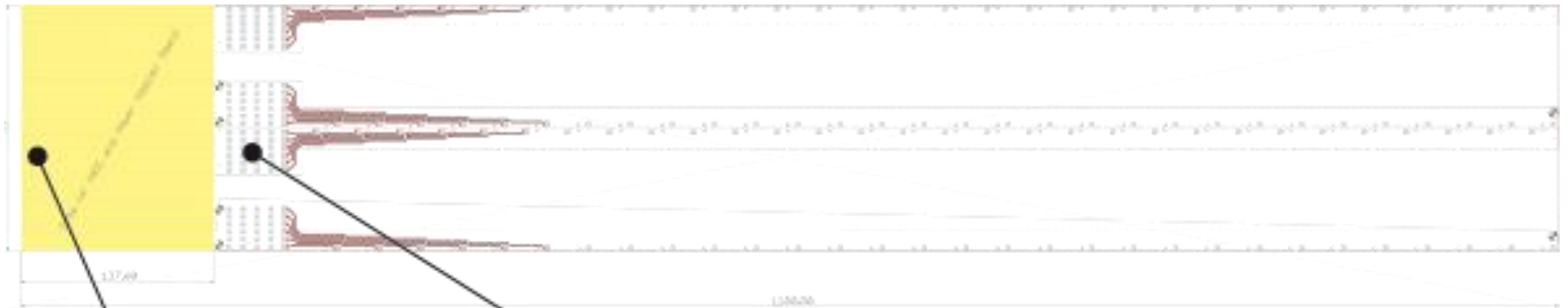
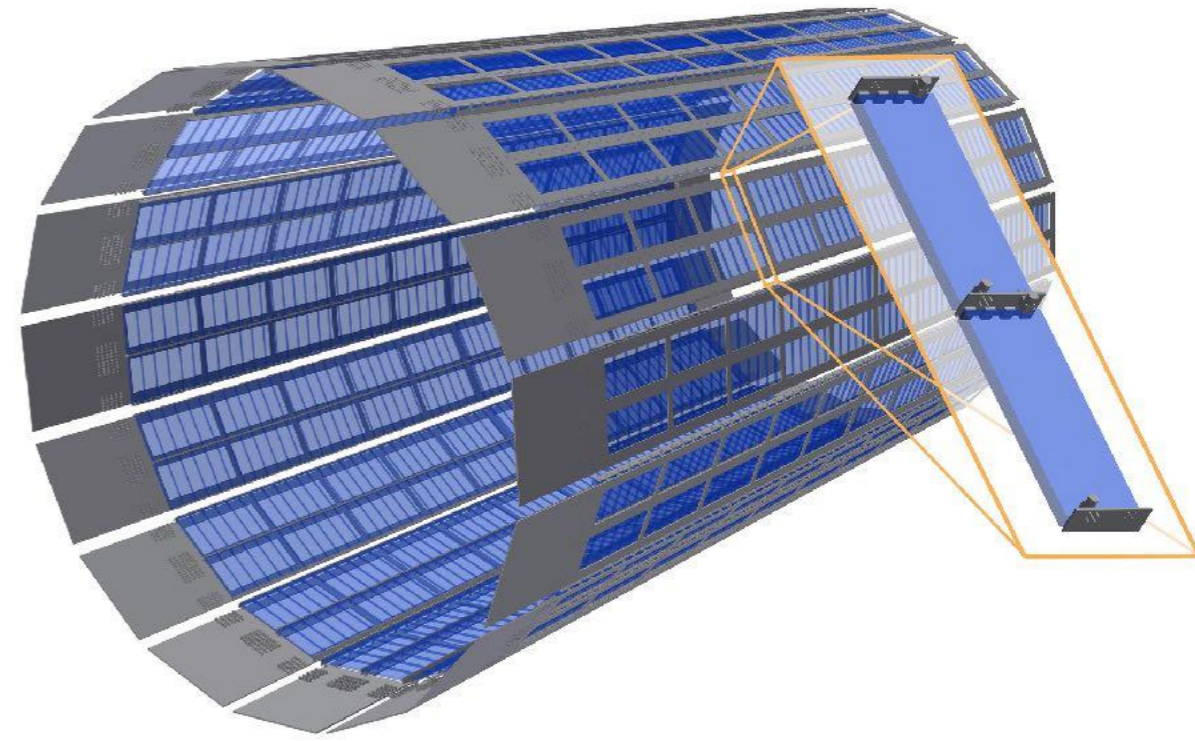


- between the Barrel DIRC and the EMC
- high efficiency to charged particles
- blind to γ s



Super Module

- a half length prototype



Space for FEE implementation

MMCX connectors (Signal Out)

Dual-module



900 mm

Large PCB (railboard) production issue & Delivery Delay (3.5 months late)



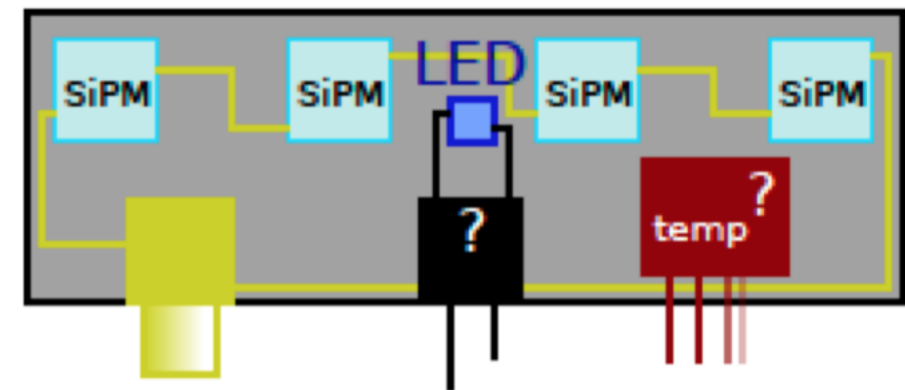
Half-length was not a problem. Full length is. Production at CERN?

Monitoring and Calibration

- Voltage and current monitoring
 - the primary parameter that influences the characteristics of SiPM
 - general health check
- Temperature
 - SMD PTC on the sensor-board
 - relative: 200 mK, absolute: 4 K
- Gain
 - DCR: 10-100 kHz/mm²
- LED calibration system
 - SMD LED on the sensor-board

Model	V_{BD}	gain
KETEK	18 mV/K	< 0.5 %/K
Hamamatsu S13360	50 mV/K	~ 1.3 %/K
AdvanSiD NUV	26 mV/K	< 1 %/K

Table 4.5: A short summary of temperature dependencies of SiPM characteristics. Values are taken from Ref. [10, 11, 12, 13]. The temperature dependence of break-down voltage of KETEK device is evaluated at 5 V over-voltage. Note that the absolute temperature coefficient of the gain is smaller at higher over-voltage. According to Ref. [10], the coefficient will be -0.7% at 2 V over-voltage.



SciRod (Erlangen) cont'd

More Time Resolutions (2)

Scintillator 5 x 5 x 50 mm³

Scintillator	MPPC	left		center		right
		σ_t	σ_t	σ_t	σ_t	σ_t
BC408	S10362-100P	68		103		74
	S12572-050P	74		67		68
BC420	S12572-050P	78		64		51

Scintillator 5 x 10 x 50 mm³

Scintillator	MPPC	left		center		right
		σ_t	σ_t	σ_t	σ_t	σ_t
BC408	S10362-100P	113		123		92

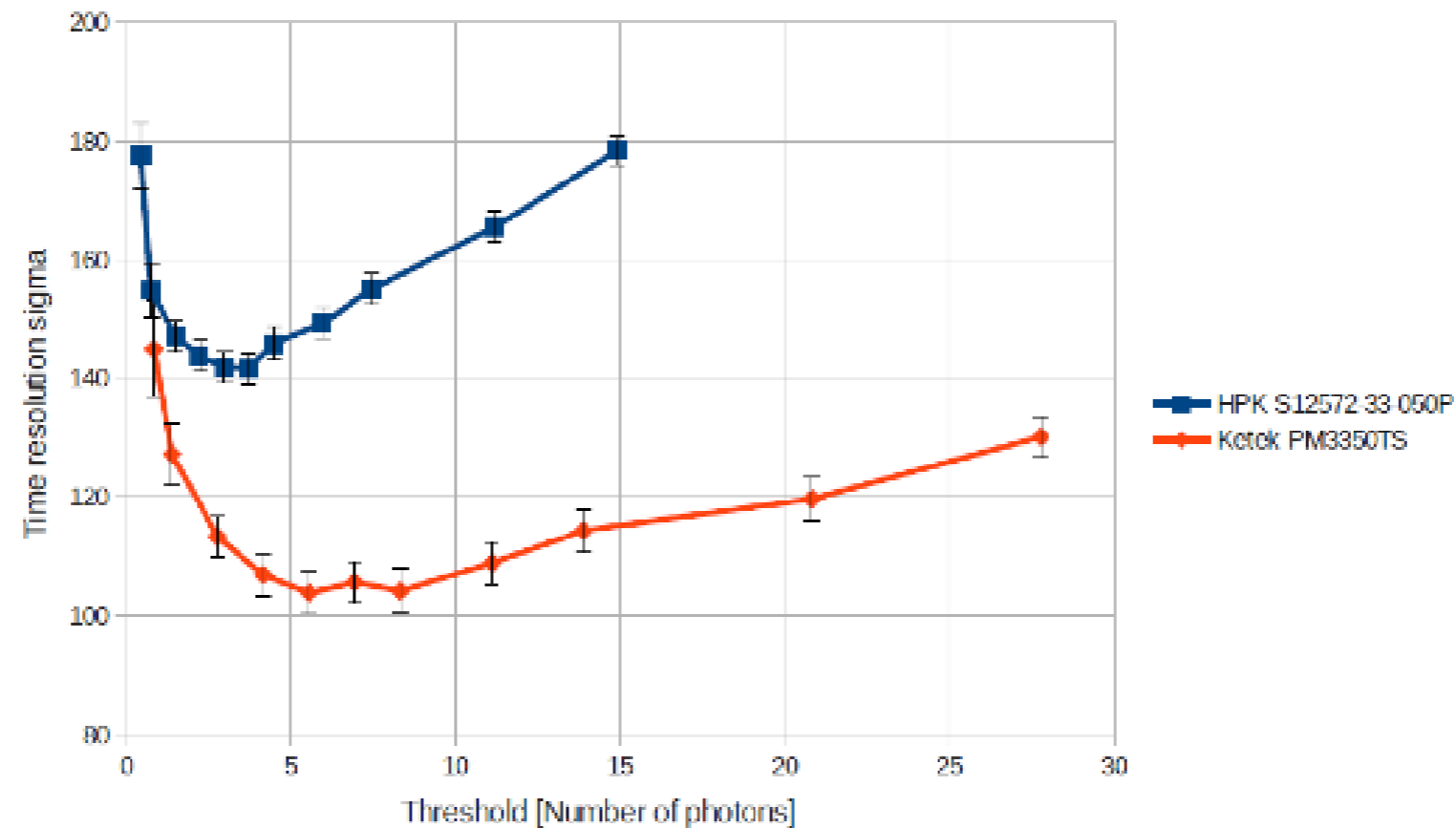
Scintillator 5 x 5 x 170 mm³

Scintillator	MPPC	left		center		right
		σ_t	σ_t	σ_t	σ_t	σ_t
BC408	S10362-100P	88	85	129	85	99

Longer and wider rods tend to give worse time resolution

The best time precision when triggering on the first photon? Analog SiPM

Time resolution of a scintillator tile read-out with the Hamamatsu SiPMs

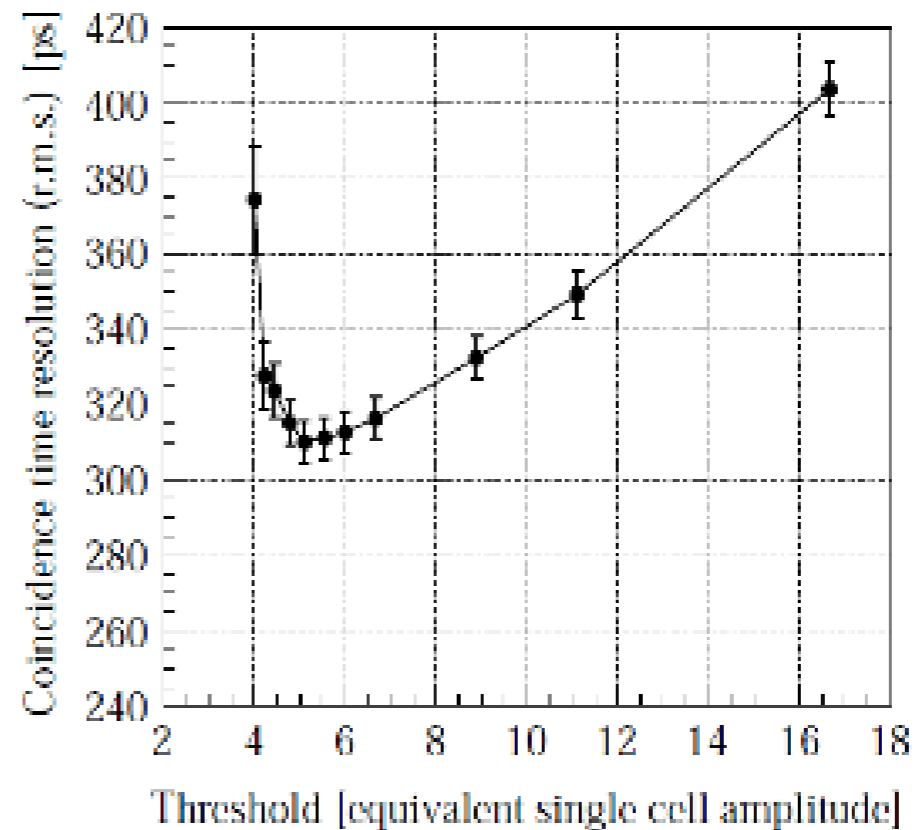
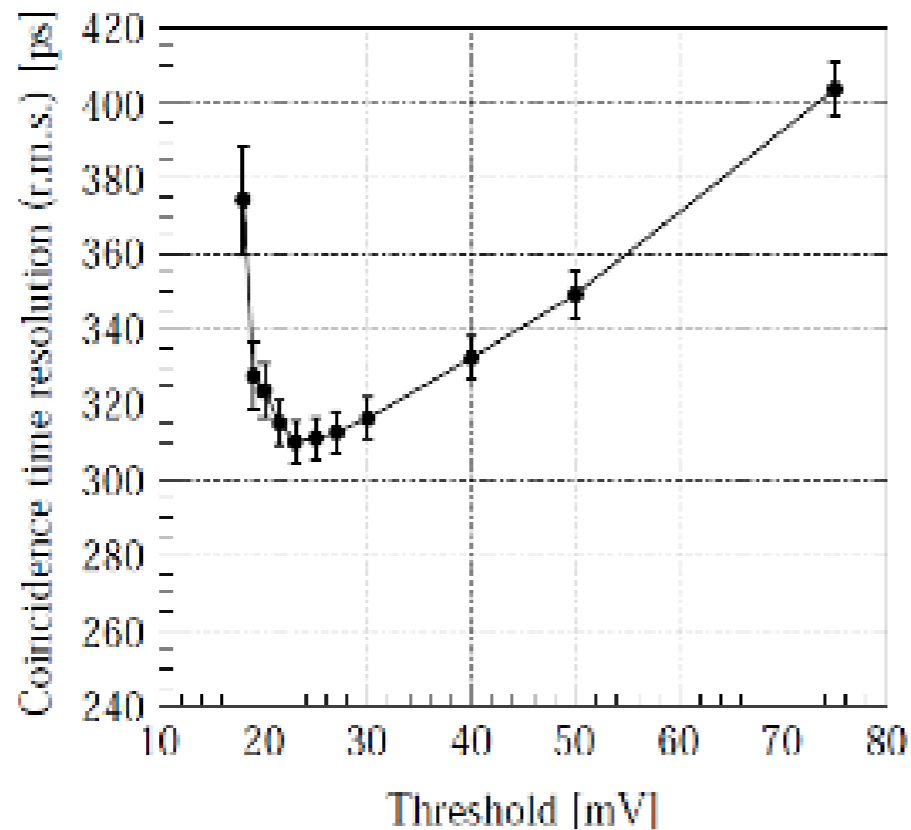


No, the trigger threshold should not be set to the first detected photon, due to electronics noise and the SPTR of the SiPM.

The best time precision when triggering on the first photon? Analog SiPM

For analog SiPMs, this behaviour is changed due to electronics noise and the SPTF

Time resolution of a scintillator tile read-out with the Hamamatsu SiPMs



No, the trigger threshold should not be set to the first detected photon

SPTR of SiPMs

2 options: Hamamatsu or Ketek (3x3 mm²)
AdvanSiD: worse timing, low PDE

SensL: also lower PDE

Ketek with optical trenches showed best results

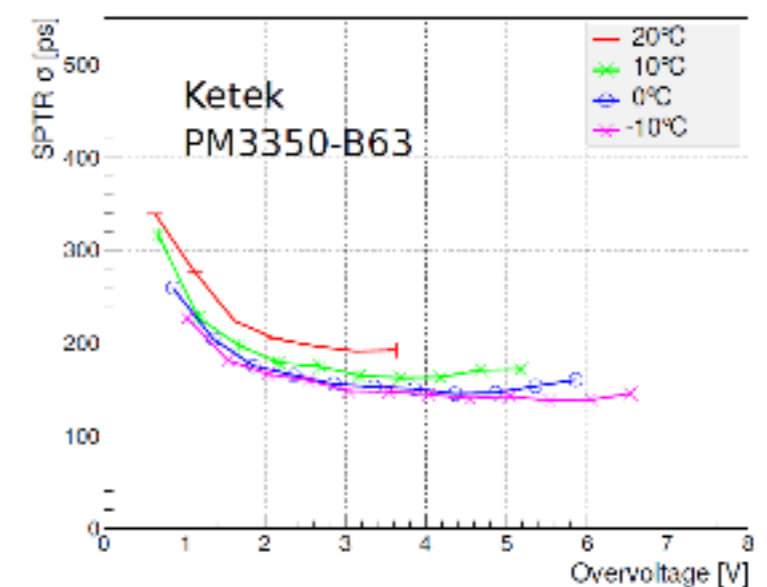
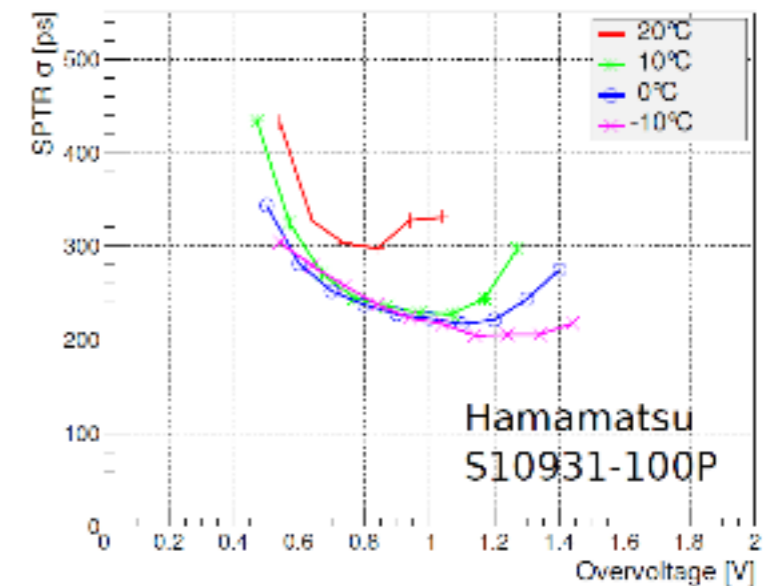
Time resolution follows $1/\sqrt{N}$

We expect ~ 60 photons per SiPM:

Hamamatsu 100P → $\sigma \sim 40$ ps

KETEK PM3350 → $\sigma \sim 25$ ps

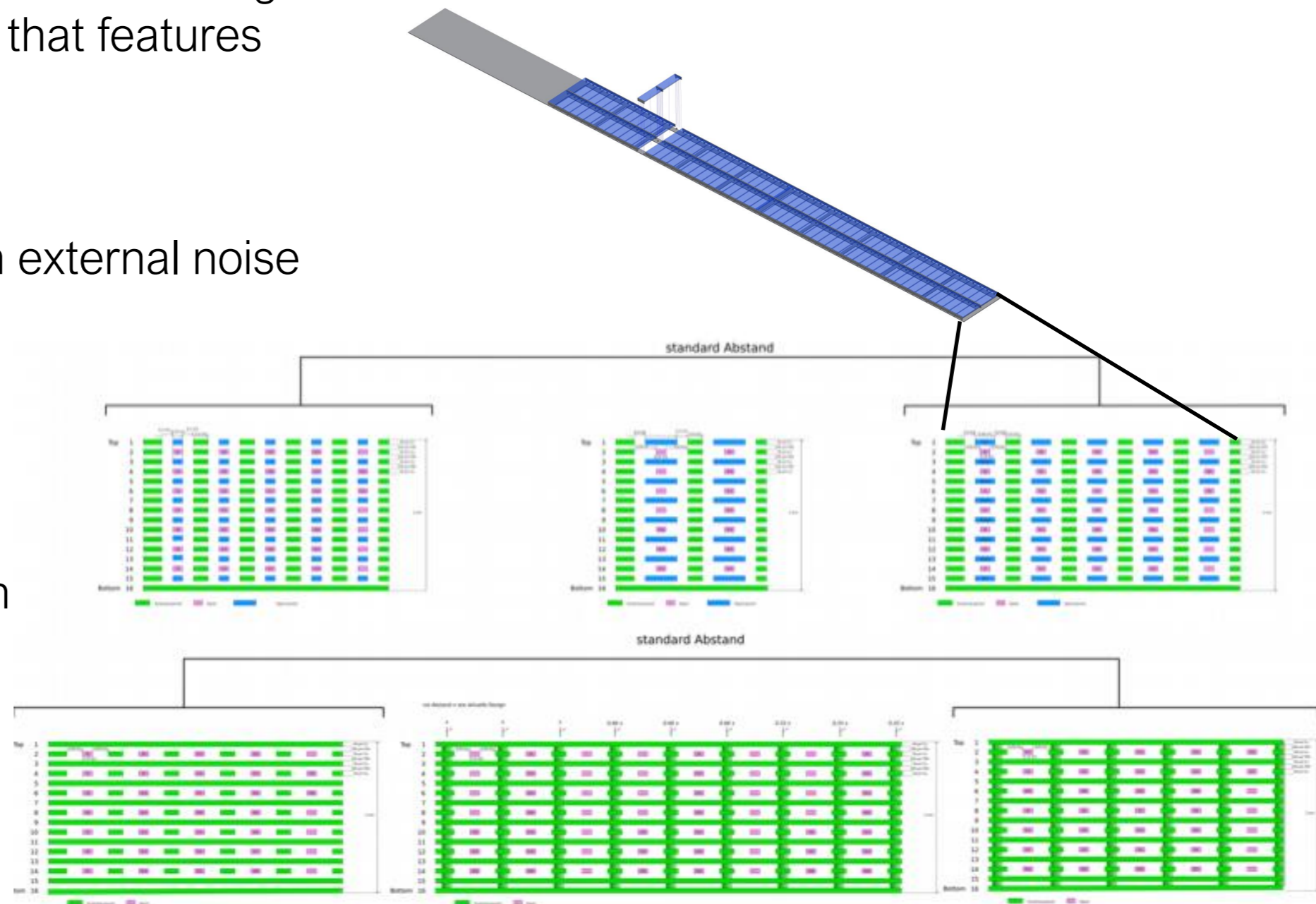
SPTR



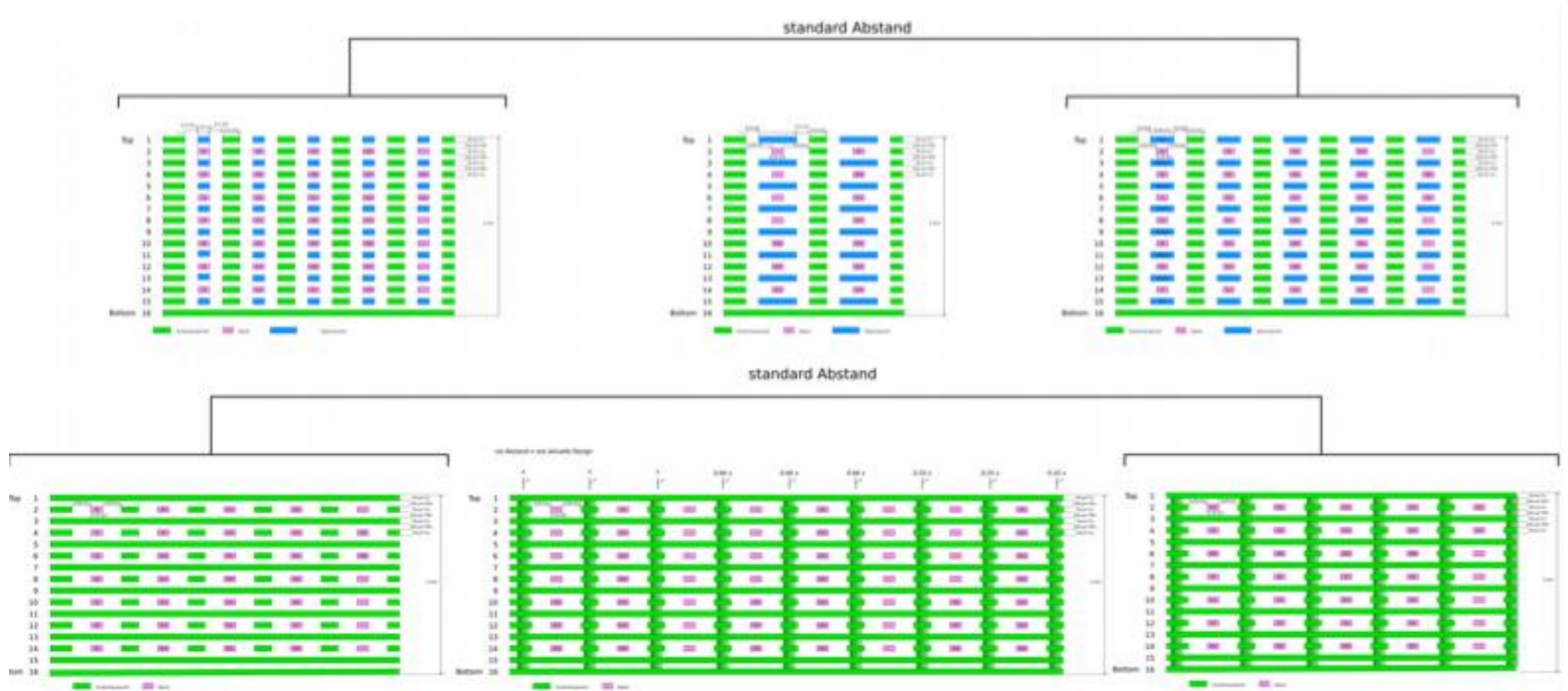
“Time resolution below 100 ps for the SciTil detector of PANDA employing SiPM”
with picosecond pulsed laser (400 nm)

Micro Stripline Technique

- Coaxial-like structure to transmit signals over a PCB board realised on a multilayer PCB board, that features
 - High density
 - Good shielding from external noise
 - High bandwidth
 - Low crosstalk
 - Mechanical strength

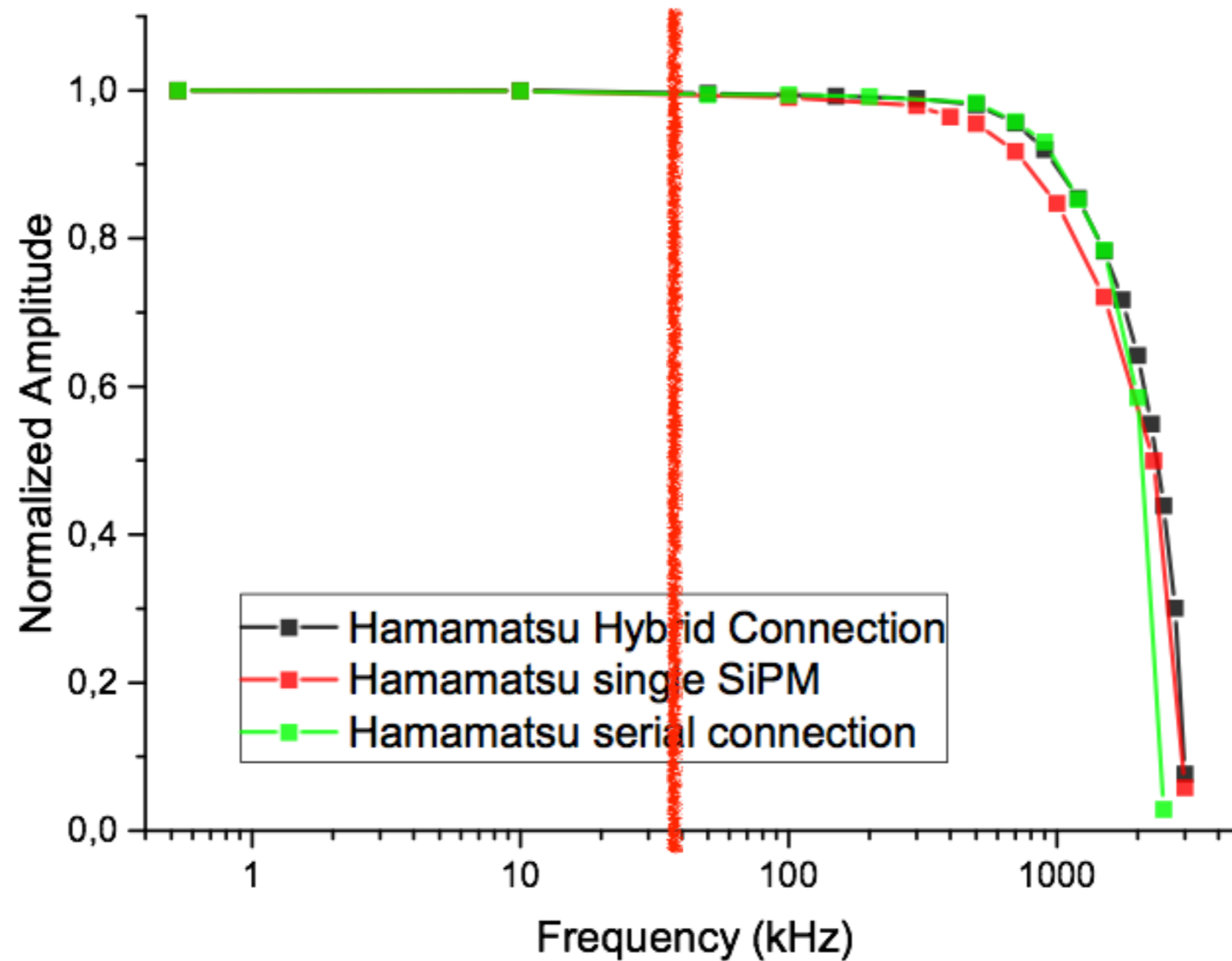


Complementary Designs Railboard v2.

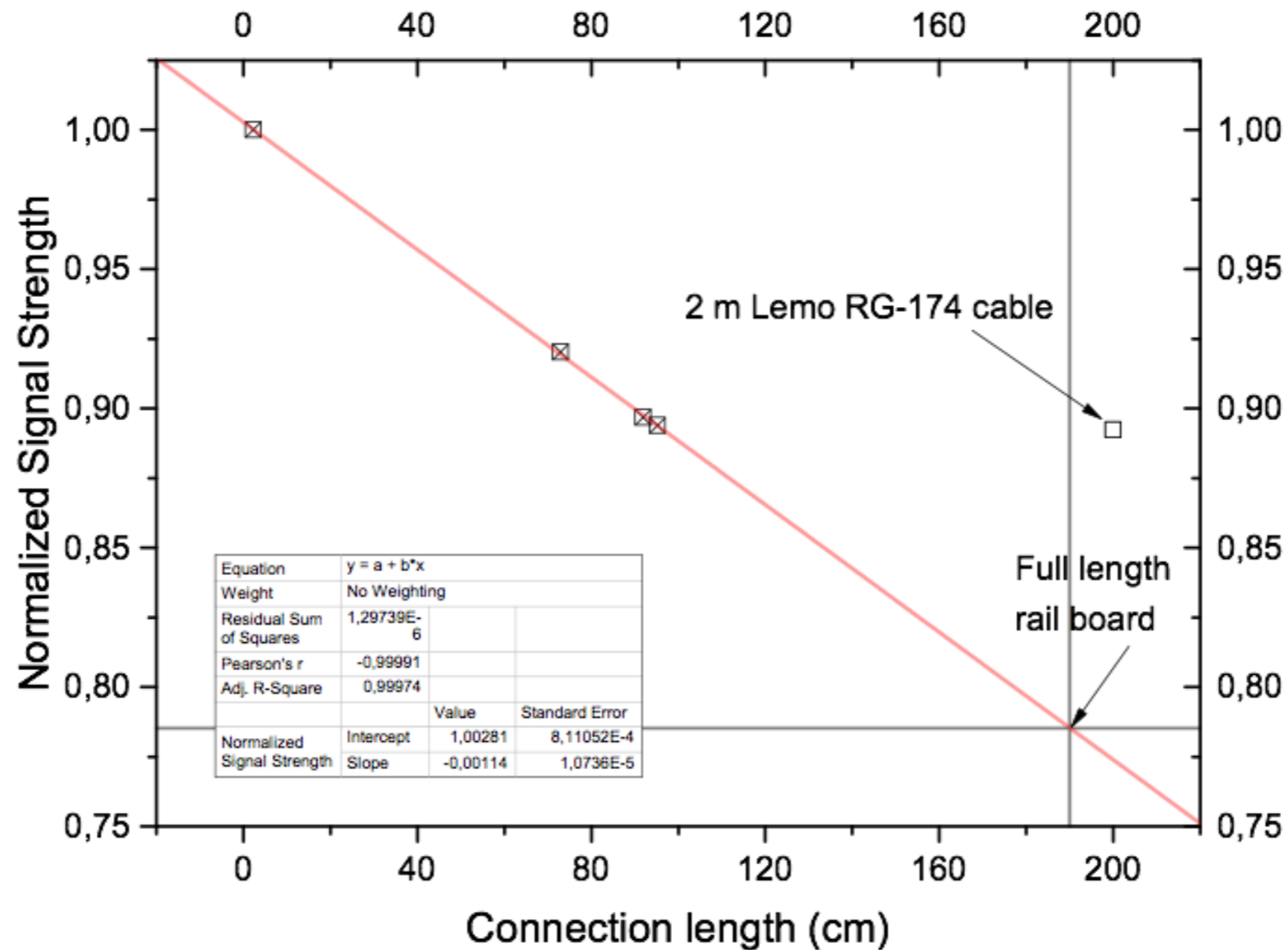


Rate Capability

Max. tile hit rate



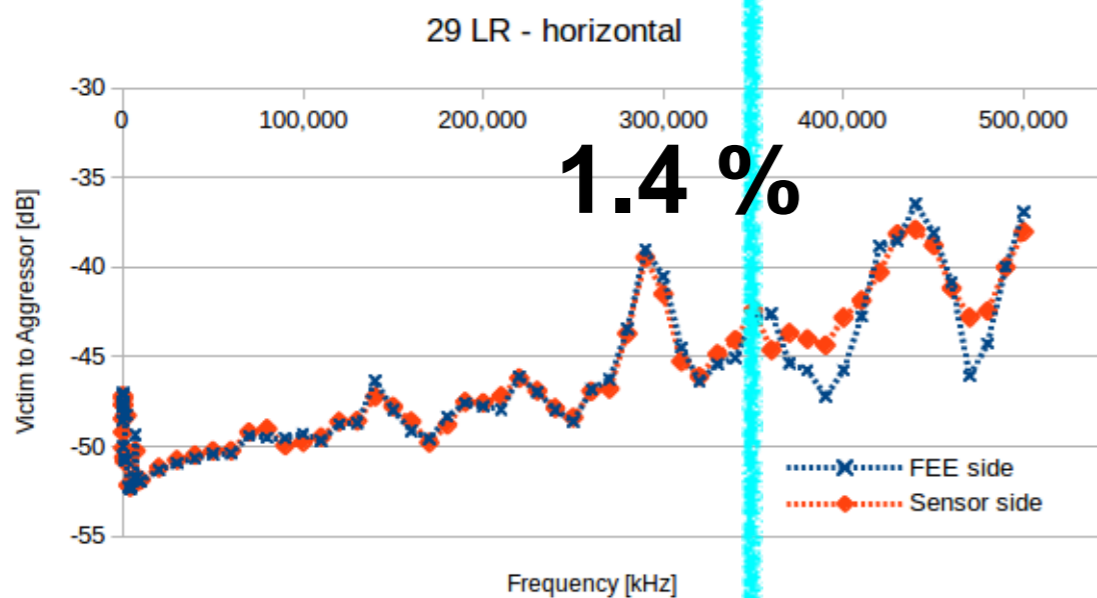
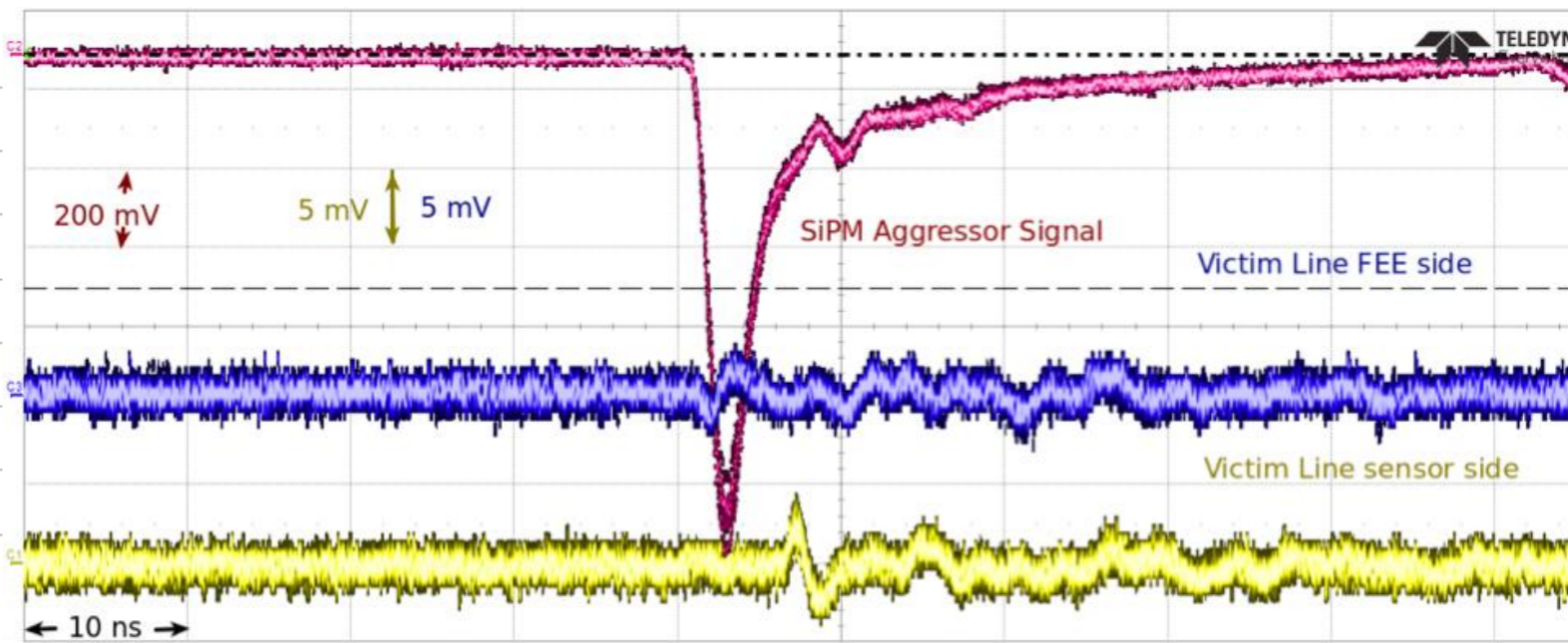
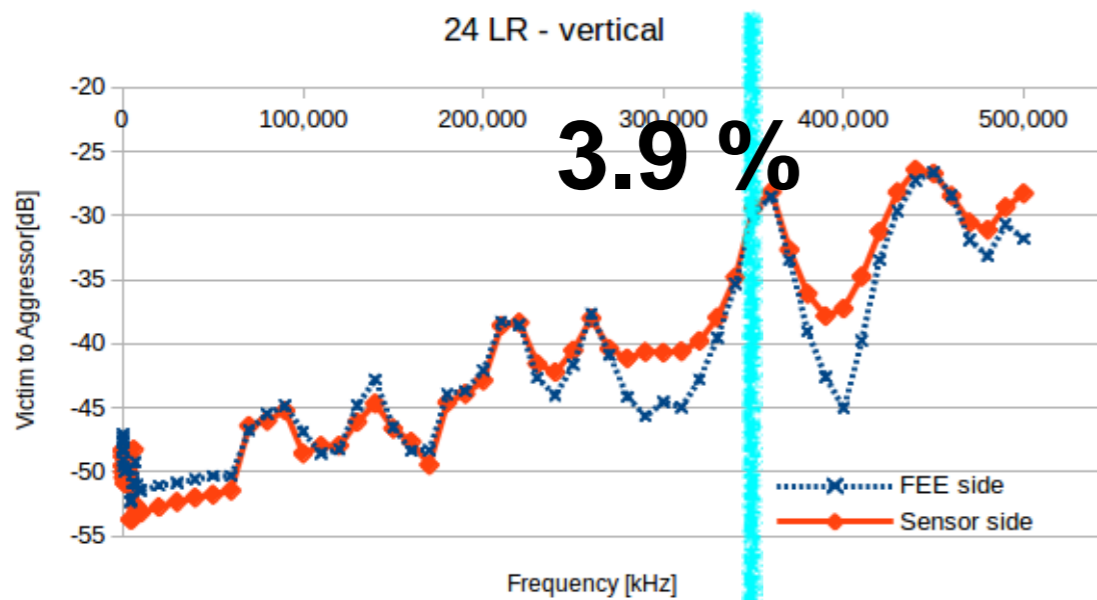
Signal Attenuation on the Micro Striplines



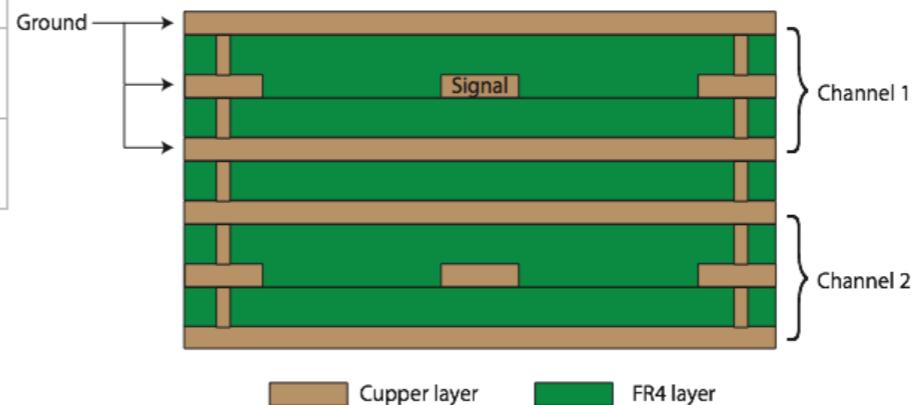
Attenuation can be reduced by increasing the cross section of the signal

Crosstalks between Micro Striplines

1 ns rise time



Crosstalks can be reduced e.g.
by using “via” and/or
by optimising the ch. sequence

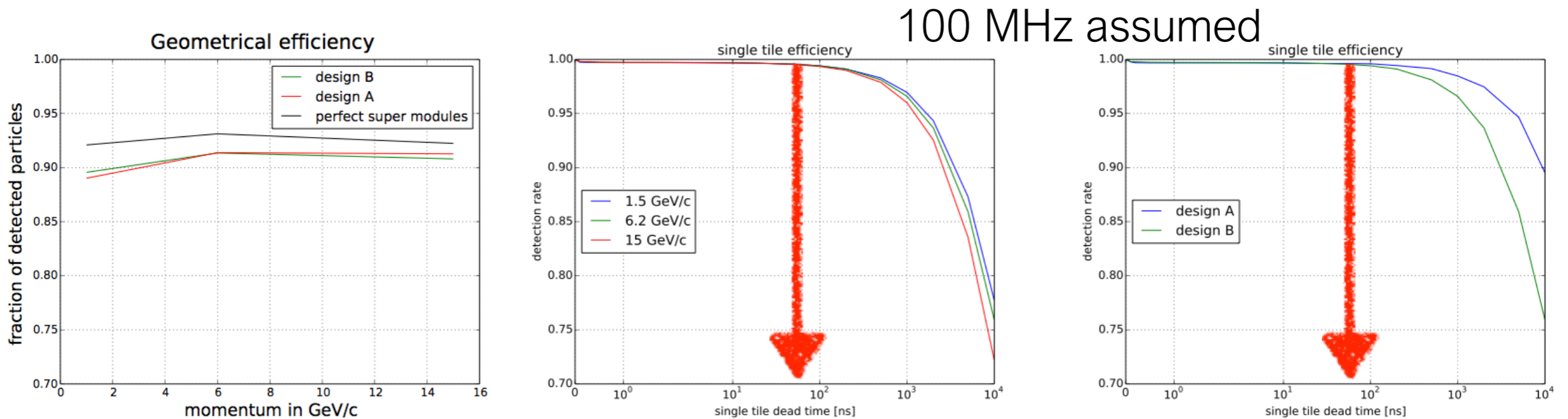
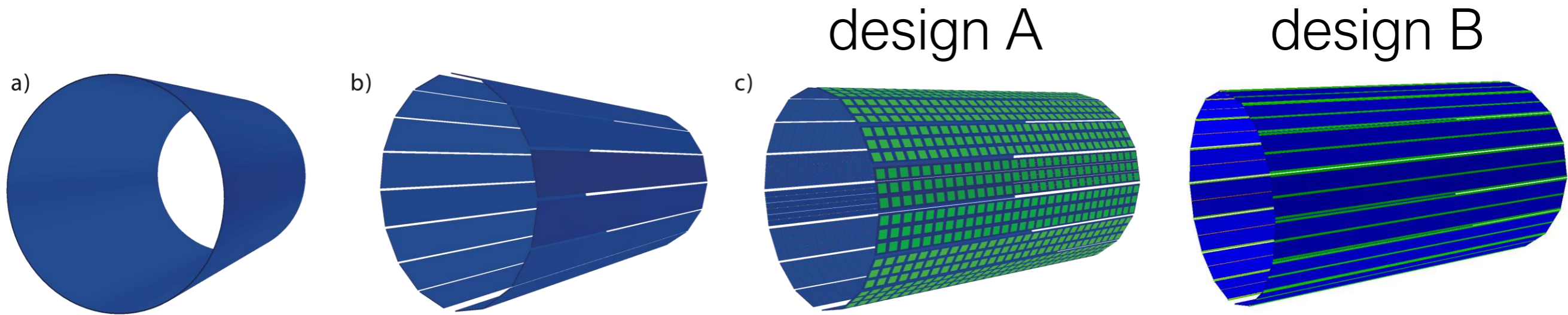


1	6	11	16	21	26
2	7	12	17	22	27
3	8	13	18	23	28
4	9	14	19	24	29
5	10	15	20	25	30

Efficiency

geometry	number of tiles	tile size mm^2	active area m^2	fill factor
reference	1	-	5.7	100 %
perfect super-modules	16	180×1800	5.2	91 %
design A	5760	28.5×28.5	4.7	82 %
design B	1920	86.95×29.4	4.9	86 %

Table 5.1: Properties of the studied Barrel TOF design options.

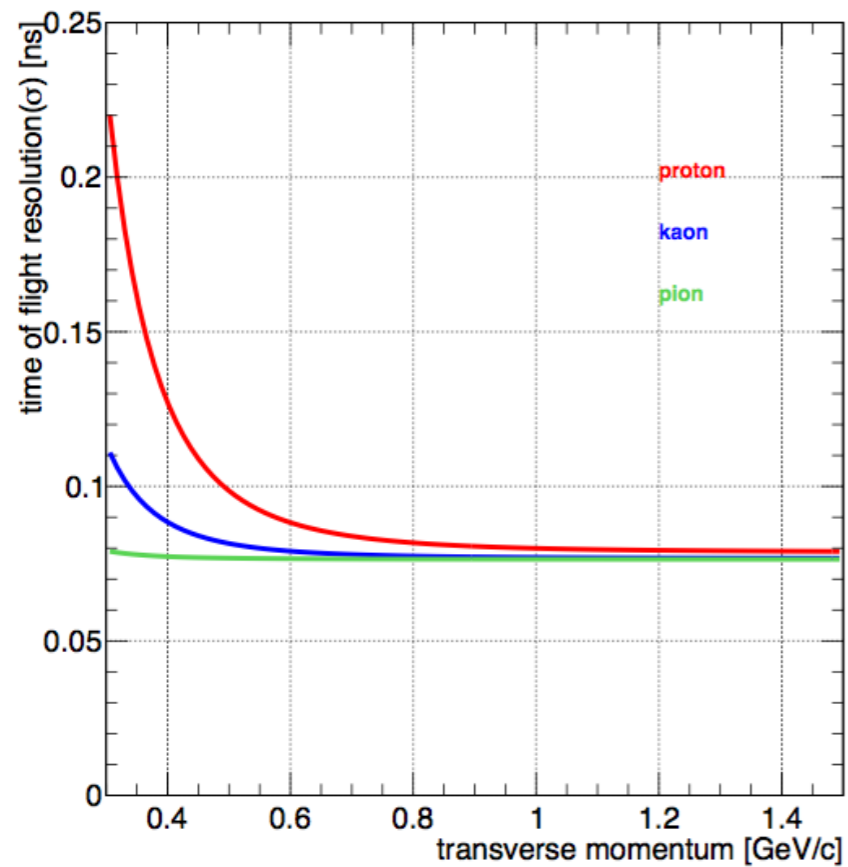


Sensor recovery time: ~ 50 ns, TOF-PET chip > 300 kHz average through-put,
 Max tile hit-rate is ~ 40 kHz, TOF-PET chip has a buffer (4 hits) to cope with
 locally high-rate events

TOF-based Particle Identification

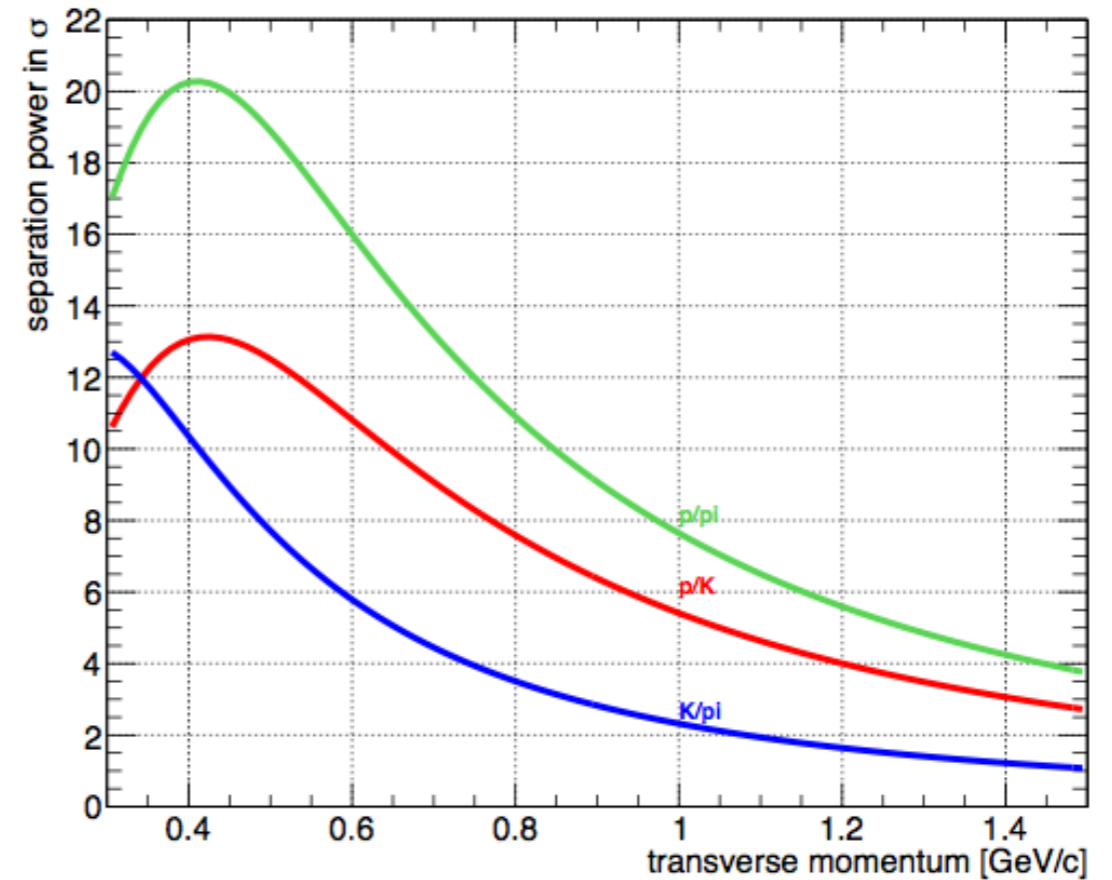
$$n_\sigma = \frac{|tof_p - tof_K|}{\max(\sigma_p, \sigma_K)}$$

time of flight resolution



from simulation

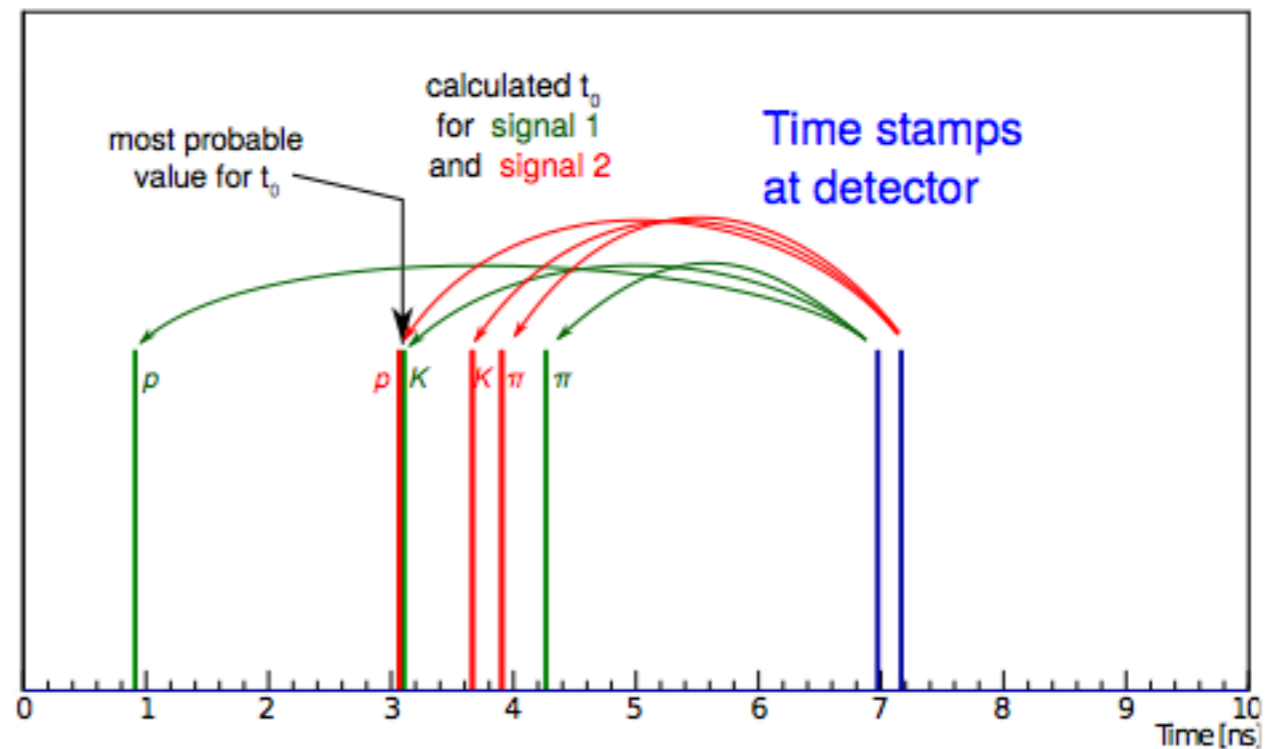
separation power



Relative TOF

Basic principle

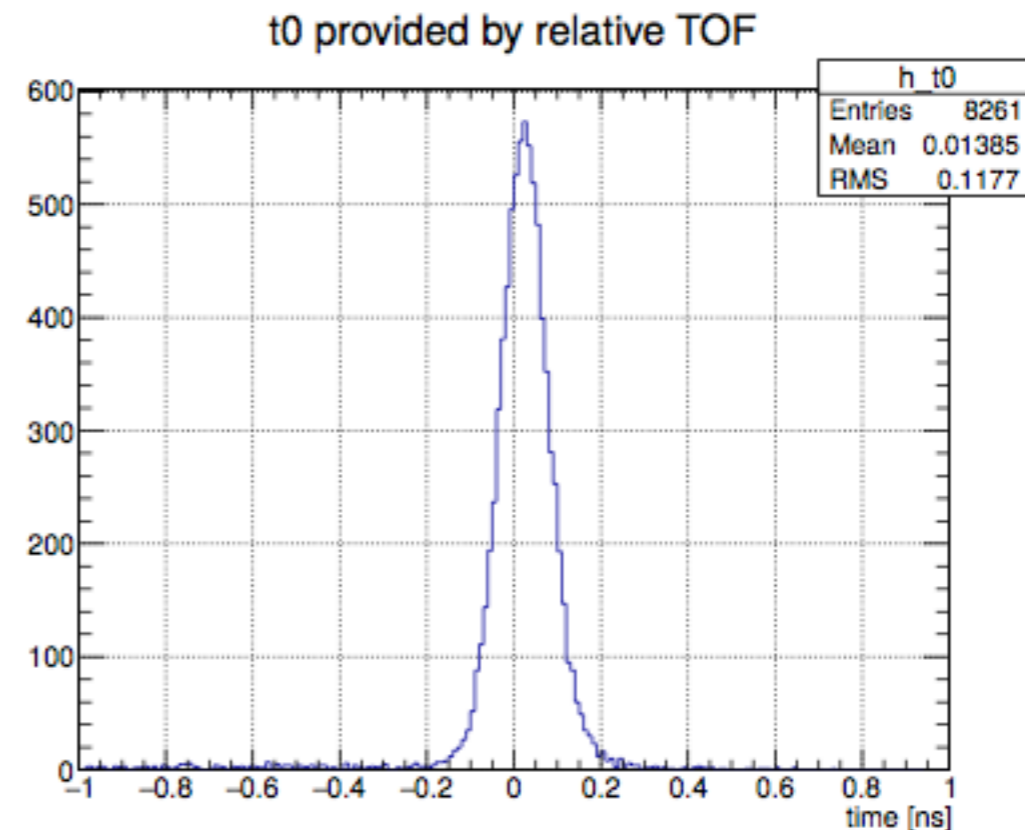
- Calculate t_s for all possible particle species and all N tracks
 - Using reconstructed track parameters
 - p, K, π, μ, e
- evaluate all 5^N mass configurations
 - Compare their X^2 weights
 - Select the “most probable”



Relative TOF

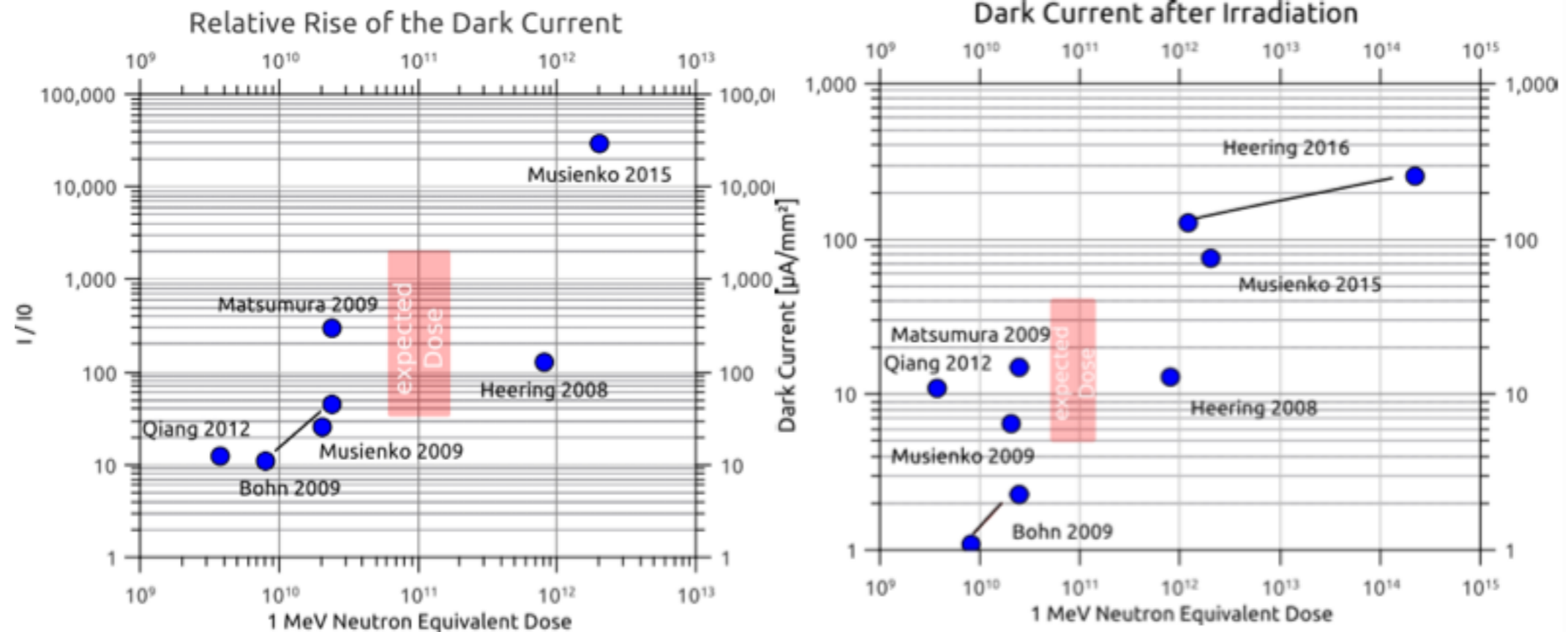
t0 determination in Pandaroot

- Relative Tof algorithm implemented in local macros
 - Pid stage
- DPM generator
- Events with N>3 **primary** tracks matched with SciTil
- **Mismatched tracks are rejected (MC information)**



Radiation Hardness of SiPMs

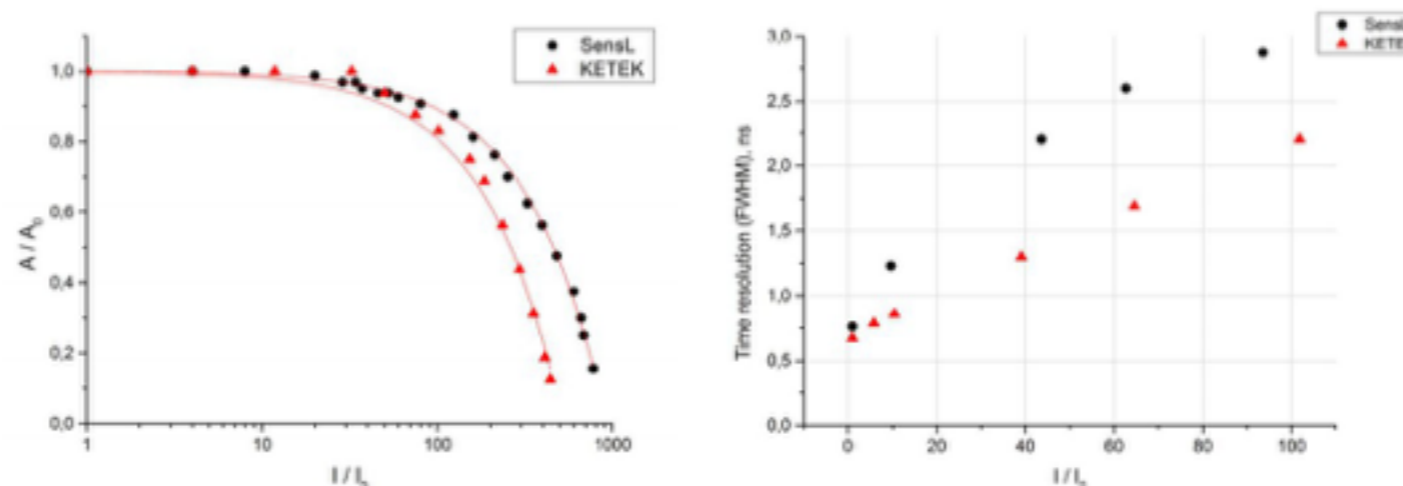
Summary of the Literature Study



Radiation Hardness of SiPMs

Simulation of dark current increase

- Study done by V.A. Kaplin et al., *"Time and Amplitude characteristics of large scintillation detectors with SiPM"* -2015
- **Dark current increase simulated** by continuous low intensity illumination by an LED



Radiation Hardness of SiPMs

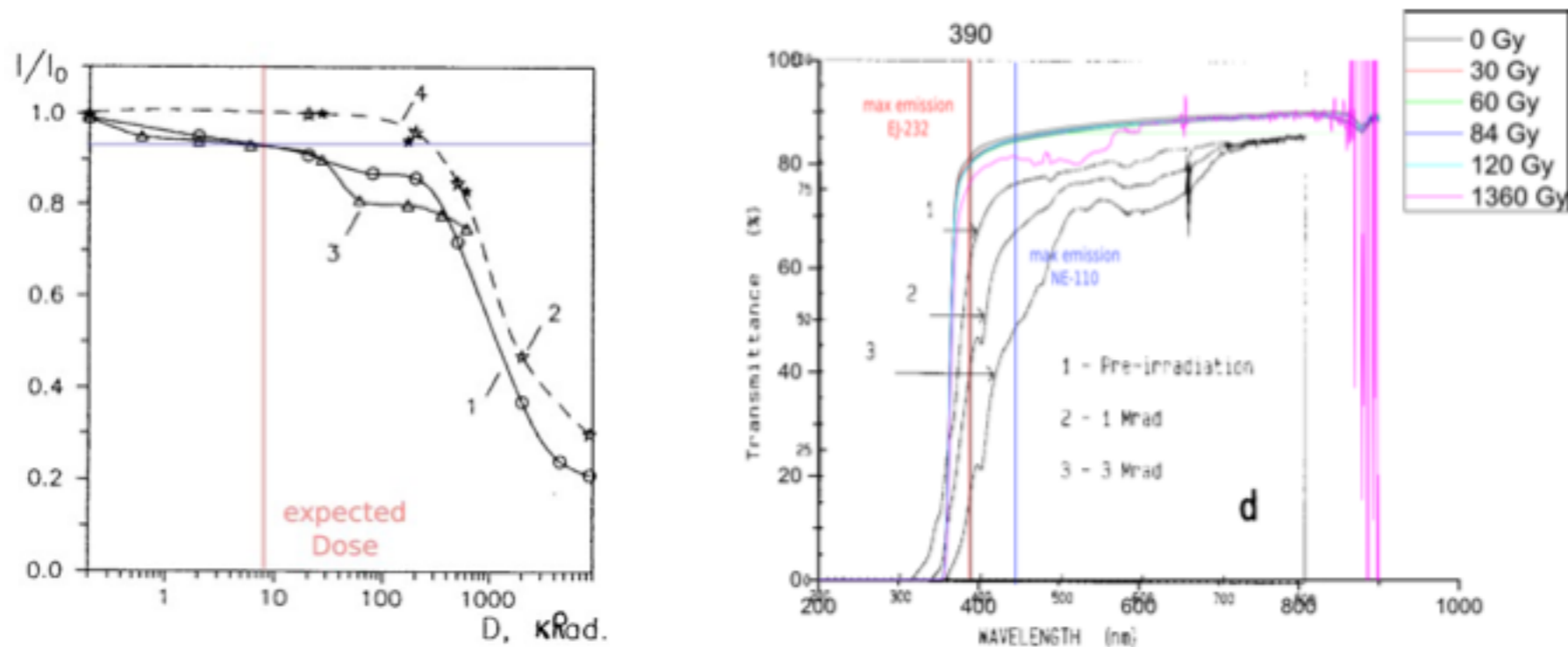
Time resolution expectation

- Expected current between 8 and 40 $\mu\text{A}/\text{cm}^2$
- For 3x3 mm^2 sensors: up to 360 μA
- Taking the measurements of KETEK and SensL sensors as a reference we expect deterioration of the time resolution by ~30% to ~70% over 10 years
- Reduced pixel dead time should reduce the effect of the radiation
 - Hamamatsu: 50 ns, KETEK & SensL: >200 ns
- True impact however is not known

Radiation Hardness of Scintillator Material

Scintillator Radiation Damage

Irradiation with Co^{60}



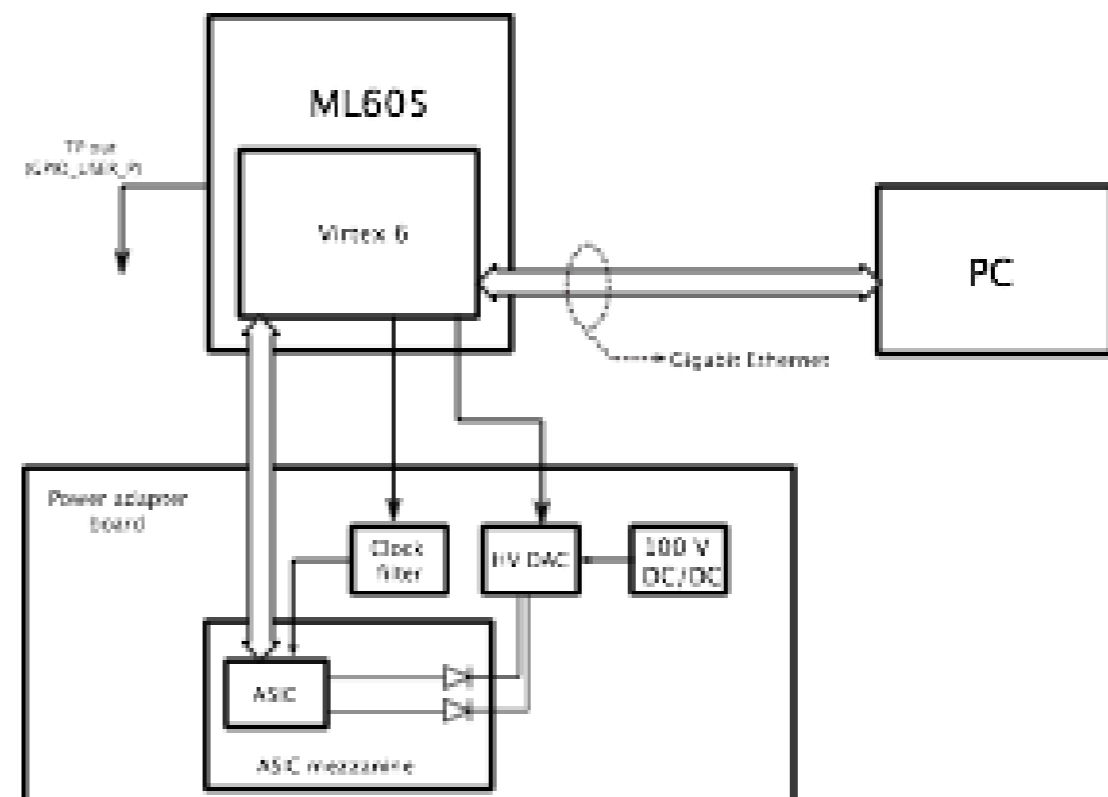
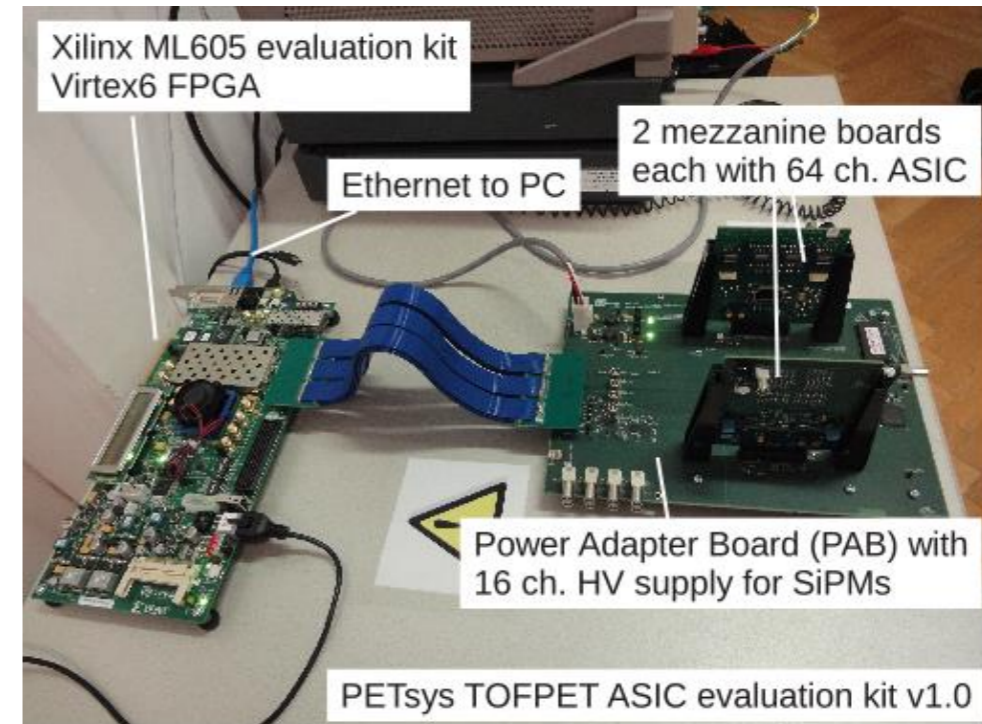
Expected dose ~ 8.4 kRad

Front End Electronics, DCS

TOFPET ASIC by PETsys Electronics

number of channels	64
TDC time binning	50 ps (25 ps optional)
intrinsic time resolution	21 ps r.m.s.
charge measurement	time over threshold (ToT)
dynamic range	300 pC
SNR ($Q_{in} = 200$ pF)	25 dB
coarse gain	G0, G0/2, G0/4
SiPM family support	positive or negative signal polarity
on-chip calibration circuit	internal pulse generator, programmable 6-bit amplitude
max channel hit rate	160 kHz
max output data rate	320 Mb/s (640 Mb/s with double data rate)
Fully digital output	2 data LVDS links, DDR compatible
operation frequency	80-160 MHz
power per channel	8-11 mW
SiPM HV fine biasing	range 500 mV

Table 4.2: Summary of the specification of the TOFPET ASIC by PETsys.



Monitoring and Calibration

- Voltage and current monitoring
 - the primary parameter that influences the characteristics of SiPM
 - general health check
- Temperature
 - SMD PTC on the sensor-board
 - relative: 200 mK, absolute: 4 K
- Gain
 - DCR: 10-100 kHz/mm²
- LED calibration system?
 - SMD LED on the sensor-board

Model	V_{BD}	gain
KETEK	18 mV/K	< 0.5 %/K
Hamamatsu S13360	50 mV/K	~ 1.3 %/K
AdvanSiD NUV	26 mV/K	< 1 %/K

Table 4.5: A short summary of temperature dependencies of SiPM characteristics. Values are taken from Ref. [10, 11, 12, 13]. The temperature dependence of break-down voltage of KETEK device is evaluated at 5 V over-voltage. Note that the absolute temperature coefficient of the gain is smaller at higher over-voltage. According to Ref. [10], the coefficient will be -0.7% at 2 V over-voltage.